# EXHIBIT H

# WAFER FAB GROUP

# 2001 BUDGET

# 2001–2003
# 3-YEAR PLAN

AMD

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# Advanced Micro Devices, Inc.

# 3 Year Plan Commentary

# Wafer Fabrication Group

## December, 2000

AMD

# Wafer Fabrication Group

## 3 Year Plan Commentary

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# 1. Executive Summary

**Overview: Mission, Capabilities, Current Situation and Summary of WFG's Strategy to Win**

The mission of the Wafer Fabrication Group (WFG) is to provide wafer production support to the Computation Products Group (CPG) and the Memory Group (MG) that meets their performance, volume, cost, quality and service requirements.

The WFG consists of the Fab 14/15 and Fab 25 in Austin, Texas, Fujitsu/AMD Joint Venture (FASL I, II, III, Iwate and GMD, in Gresham, Oregon), AMD Saxony Manufacturing GmbH (Fab 30, Dresden, Germany) and external suppliers (Epson, Motorola, Sony, TSMC, UMC and IBM).

The most important priorities facing wafer fabrication in 2001 will be the continued successful ramp of Fab 30, while preparing the next-generation 0.13µ HiP7 technology for Athlon and Hammer products; the supply of Athlon product (mostly Duron) from Fab 25 at the proper speed mix, while supporting the transistor development to increase the frequency performance to ~ 2 Ghz by yearend and enabling a low power mobile part in 1Q2001; and, build out of sufficient Flash capacity (JV3, GMD) to stabilize/grow market share, while ramping into production the next-generation CS59 (0.18µ) technology for high density NOR Flash products.

One of the most critical strategic issues is the definition of a capacity plan that matches the technology and volume requirements of CPG. The microprocessor unit demand fully utilizes Fabs 25 and 30 through 2001 and most of 2002, but is significantly short of full utilization of Fab 25 (<50%) in 2003.

The plan capacity had been built around a strategy to convert Fab 25 to copper/0.13µ technology to provide sufficient volume capability through 2003 and beyond. However, this plan will be abandoned in favor of converting Fab 25 to Flash production, starting in 2002. As a result, microprocessors unit volume requirements that cannot be satisfied by Fab 30 alone will be met by external foundries, starting in 2002. Finally, the need for additional capacity beyond the three year horizon is expected to be met by a new facility (Fab 35), currently in the planning phase.

Wafer fabrication at AMD has advanced to the level that few, if any, in this industry have achieved. Fab 25 performs at high volumes and high yields, while exhibiting extraordinary flexibility to move the process to the "edge" of process capability, with good control. On-line process development, alongside volume production, enables more rapid technology and product performance advancements, and has played a major role in AMD's ability to achieve the edge over Intel. This capability has been transferred to Fab 30, with similar results already being achieved.

Combining high volume, cost effective manufacturing, with heavy development focus, and outstanding manufacturing control, has become a hallmark of AMD wafer fabrication.

## 1.1 Fab 14/15

Fab 14/15 mission is to support AMD's business segments requiring a complex mix of CMOS Logic, High Density Programmable Logic, Non-Volatile Memory, and BiPolar. Internal customers supported by Fab 14/15 include Network Products Division (NPD), Embedded Products Division (EPD), and Non-Volatile Memory Division (NVD). External customers include Lattice and Legerity. Based on current demands from these customers, Fab 14/15 is at or near capacity for the next 3 years.

The 2001 focus will be the ramp of the Bipolar HV-4 and the development and initial production ramp of the Bipolar HV-7 technologies for Legerity.

Fab 14/15 will transition from 56% of its wafer out volume for internal customers to 22% by 2003. Fab 14/15 will continue efforts in wafer cost reductions and quality improvements in order to remain competitive.

## 1.2 Fab 25

Fab 25 is designed to provide state of the art microprocessors for desktop, mobile, and embedded computing solutions. In addition to its primary thrust in the CPG, Fab 25 also supports logic products for EPD. Output has been ramped to full capacity at 5000 outs/week. The technology transition to 0.18 micron will be complete in 1Q2001. Critical advanced transistor development for Fab 25 and Fab 30 is supported within the Fab 25 organization, with much of this material requiring expedited cycle times. Microprocessor ASP erosion drives continuing emphasis on defect density reduction activities to reduce die cost.

As stated earlier, Fab 25 has been preparing for the introduction of copper/0.13µ technology, which is the basis for this budget. However, since the three year microprocessor demand will not sufficiently utilize the installed capacity, Fab 25 will convert to Flash (0.18µ) production, starting in 2002. Detailed plans will be developed in 1Q2001.

## 1.3 Fab 30

The mission of fab 30 is to be AMD's leading technology high volume microprocessor production fab. Fab 30 supports leading edge microprocessors for CMD/TMD currently using 0.18 micron copper technology, transitioning to 0.13 micron copper technology by 2002. Base technologies are developed in the AMD/Motorola Alliance, with auxiliary development occurring in the SDC. Transistor developments are supported in Fab 30 in close conjunction with transistor development in Fab 25.

Keys to success is the ability to rapidly insert the leading edge technology into production while ramping the fab to full capacity and maintaining the highest yields possible. After achieving initial production output in 2000, Fab 30 will ramp to 140K wafers out in 2001, 220K wafers out in 2002, and 260K wafer outs in 2003.

Primary focus for 2001 will be to execute flawlessly in meeting the production ramp and the technology transition to 0.13 micron. Additional focus must be placed on keeping Athlon competitive in 2001, reaching 2 ghz by 4Q2001 (key strategies are transistor development and Athlon on HiP7), and getting K8 into production (key strategy is implementing HiP7 SOI technology).

The primary competitor to AMD and hence Fab 30 in microprocessors is Intel. Since Intel has much more capital to invest in capacity and development, many more engineers employed in these tasks, and multiple production fabs available for capacity, other key strategies are flexibility and speed. Fab 30 is being equipped "just in time", i.e. equipment is being purchased at the last possible moment to enable the most advanced equipment to be selected and installed. Systems have been developed and deployed to allow the process technology in Fab 30 to be quickly and frequently changed as technology is developed and learned. Significant investments in factory systems, in-line process control, advanced process control, and, of course, training to be able to use these systems are key elements of the "flexibility and speed" strategy.

## 1.4 Foundry Services

The mission of Foundry Services is to provide an external manufacturing supply of wafers to those divisions that are not fully supported with internal capacity. Capacity limitations, technological availability, and strategic priority drive the requirement for external support. Historically, AMD's use of foundries was driven by opportunistic capacity not met by internal fabrication. Today, foundries are being positioned to provide capacity such that it may not be necessary to supply 100% of the volume needs internally. This should enable more effective utilization of existing factories, while avoiding capital expenditures.

The role of the Foundry Services organization is to manage the wafer foundry programs from technical feasibility through mature production. In the production phase, Foundry Services is responsible for the schedule and delivery of products from the foundries, while ensuring conformance to quality requirements and cost targets.

The foundry network consists of:

**Epson**. Epson will continue production through the year 2001 at the Fujimi Japan production facility on five and six-inch wafer processes in support of the EPD product requirements.

**Foundry for Athlon**. This foundry will provide 0.13-micron microprocessor capacity starting in the year 2002 for the CPG. The purpose is to provide an early source of Athlon product on 0.13µ technology to augment the 0.13µ capacity from Fab 30.

**Motorola**. Motorola C4 evaporated bump manufacturing capacity will continue to be utilized at the Austin facility until the internal AMD bump capacity can support the total bump requirement. Bump

production at Motorola is planned to continue through 2Q2002, with volumes projected to range between 15K – 25K per quarter.

**Sony Semiconductor Company of America.** Sony will continue production at its San Antonio production facility through the year 2001 in support of low volume EPD product requirements.

**Taiwan Semiconductor Manufacturing Company (TSMC), Taiwan.** TSMC will continue production in support of low volume NPD product requirements.

**United Microelectronics Corporation (UMC), Taiwan.** UMC will be used to support NPD, EPD and the Chip Set (PPD) requirements.

## 1.5 Fab 35

Long-range CPG projections indicate that additional capacity will be needed in the 2004-2005 timeframe. This will be a 300mm factory, and will require substantial advance planning to execute properly.

Fab 35 will likely startup as 100 nanometer technology and will employ the newest manufacturing technology. The plant will be highly automated and will rely heavily on Advanced Process Control and manufacturing systems currently under development in WFG.

This project will undoubtedly require a partner, to share the initial investment and absorb the capacity. Partner options are numerous but priority must be given to a technology partner. Location options are many, depending on partner; strong preference is to locate Fab 35 in Austin area, to capitalize on existing manufacturing know-how and proximity to the product line.

## 1.6 Fujitsu AMD Semiconductor, Ltd. (FASL) I, II, III

The mission of FASL is to be the cost effective volume producer of AMD and Fujitsu jointly developed flash products in support of Memory Group.

The FASL strategy is to leverage process technology, innovative products and manufacturing technology enabling AMD and Fujitsu to be the leaders in the flash memory business. FASL will support the entire technology portfolio of products...floating gate (CS59S) for high speed NOR, NROM (CS99) for low cost NOR, and NAND (CS59N) for mass storage applications.

FASL I is the volume Fab for 0.35 micron NOR products and is operating at full capacity of 7500 production starts per week. Over time, a portion of the volume will be converted to CS-99 for low-density products.

FASL II is nearing full volume (6000 wafer starts per week) of predominantly CS-49S NOR technology and a small volume of CS-49N NAND technology. Development work is currently underway for both the CS-99 NROM technology and CS-59S floating gate technology. When development is complete, the CS-

## 3.2 Advanced CMOS Logic Support - Fab 25/Fab 30

Wafers Out (k) 200mm

DIVISION

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | 2001 | 2002 | 2003 |
|---|---|---|---|---|---|---|---|
| CMD/TMD | 85.9 | 88.1 | 96.8 | 94.6 | 365.4 | 426.2 | 364.6 |
| EPD | 1.8 | 2.9 | 3.7 | 3.9 | 12.3 | 17.5 | 15.1 |
| LATTICE | 0.1 | 0.0 | 0.0 | 0.0 | 0.1 | 0.0 | 0.0 |
| **TOTAL** | **87.8** | **91.0** | **100.5** | **98.5** | **377.8** | **443.7** | **379.7** |

TECHNOLOGY

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | 2001 | 2002 | 2003 |
|---|---|---|---|---|---|---|---|
| CS-34 (3LM, 0.35u) | 1.5 | 1.6 | 2.1 | 2.0 | 7.2 | 6.2 | 4.6 |
| CS-44E72 (5LM, 0.25u) | 5.4 | 0.7 | 0.6 | 0.6 | 7.3 | 1.9 | 1.2 |
| CS-50/H6 (6LM, 0.18u) | 54.8 | 56.1 | 59.4 | 59.1 | 229.4 | 188.7 | 11.9 |
| EE7 (3LM, 0.25u) | 0.1 | 0.0 | 0.0 | 0.0 | 0.1 | 0.0 | 0.0 |
| HiP7L-bulk (7LM, 0.13u) | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 34.4 | 105.3 |
| **Fab 25 TOTAL** | **61.8** | **58.4** | **62.1** | **61.7** | **244.0** | **231.2** | **123.0** |
| | | | | | | | |
| HiP6L (6LM, 0.18u) | 26.0 | 32.6 | 38.4 | 36.8 | 133.8 | 107.4 | 0.0 |
| HiP68 (9LM, 0.13u) | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 11.8 | 0.0 |
| HiP7L-bulk (7LM, 0.13u) | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 59.7 | 66.6 |
| HiP7L-SOI (9LM, 0.13u) | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 33.7 | 190.1 |
| **Fab 30 TOTAL** | **26.0** | **32.6** | **38.4** | **36.8** | **133.8** | **212.6** | **256.7** |
| | | | | | | | |
| TOTAL | | | | | | | |
| Fab 25 Capacity Utilization | 98% | 93% | 99% | 99% | 97% | 95% | 51% |
| Fab 30 Capacity Utilization | 100% | 100% | 100% | 100% | 100% | 100% | 100% |

## 3.3 Foundries Support

DIVISION

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | 2001 | 2002 | 2003 |
|---|---|---|---|---|---|---|---|
| CMD/TMD | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 16.9 | 0.0 |
| EPD | 1.0 | 1.4 | 1.5 | 1.6 | 5.5 | 7.2 | 9.3 |
| NPD | 0.7 | 1.1 | 1.1 | 1.2 | 4.1 | 4.9 | 8.0 |
| PPD | 9.4 | 11.4 | 10.0 | 6.7 | 37.5 | 31.4 | 105.8 |
| **TOTAL** | **11.1** | **13.9** | **12.6** | **9.5** | **47.1** | **60.4** | **123.1** |

TECHNOLOGY

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | 2001 | 2002 | 2003 |
|---|---|---|---|---|---|---|---|
| 0.13u | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 16.9 | 0.0 |
| 0.18u 1P5M | 0.0 | 0.0 | 0.0 | 0.2 | 0.2 | 6.4 | 4.8 |
| 0.18u 1P6M | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 5.2 | 71.8 |
| 0.18u 5LM | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.4 | 0.9 |
| 0.18u 6LM | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.6 | 3.8 |
| 0.25u 1P4M | 9.5 | 10.2 | 8.8 | 6.0 | 34.5 | 24.6 | 36.0 |
| 0.25u 1P5M | 0.0 | 1.3 | 1.6 | 1.4 | 4.3 | 0.7 | 0.5 |
| 0.32u 1P3M | 0.2 | 0.3 | 0.4 | 0.5 | 1.4 | 1.7 | 1.7 |
| 0.35u 1P3M | 0.8 | 1.5 | 1.4 | 1.1 | 4.8 | 3.4 | 3.2 |
| 0.35u 2P3M | 0.0 | 0.1 | 0.1 | 0.1 | 0.3 | 0.5 | 0.4 |
| IMOX2 | 0.3 | 0.2 | 0.0 | 0.0 | 0.5 | 0.0 | 0.0 |
| IMOX2S | 0.2 | 0.1 | 0.0 | 0.0 | 0.3 | 0.0 | 0.0 |
| LS | 0.0 | 0.1 | 0.2 | 0.1 | 0.4 | 0.0 | 0.0 |
| SMS12 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| SMSSDL | 0.1 | 0.1 | 0.1 | 0.1 | 0.4 | 0.0 | 0.0 |
| **TOTAL** | **11.1** | **13.9** | **12.6** | **9.5** | **47.1** | **60.4** | **123.1** |
| CAPACITY UTILIZATON | 100% | 100% | 100% | 100% | 100% | 100% | 100% |

FOUNDRIES

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | 2001 | 2002 | 2003 |
|---|---|---|---|---|---|---|---|
| EPSON | 0.1 | 0.1 | 0.1 | 0.1 | 0.4 | 0.0 | 0.0 |
| FOUNDRY #1 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 16.9 | 0.0 |
| SONY | 0.6 | 0.4 | 0.2 | 0.1 | 1.3 | 0.0 | 0.0 |
| TSMC | 0.0 | 0.1 | 0.1 | 0.1 | 0.3 | 0.5 | 0.4 |
| UMC-FAB8A | 0.9 | 1.3 | 1.4 | 1.4 | 5.0 | 4.8 | 4.2 |
| UMC-FAB8B | 9.5 | 12.0 | 10.8 | 7.8 | 40.1 | 38.2 | 118.5 |
| **TOTAL** | **11.1** | **13.9** | **12.6** | **9.5** | **47.1** | **60.4** | **123.1** |

AMD

# WAFER FABRICATION GROUP

# 2001-2003 INDICES

**Version 1.0** Initial Version
10/10/00

**Fab 25:**
- Copper process initiated in 1Q02
- Plated Bump processing initiated in 4Q02

**Fab 30**
- Plated Bump processing initiated in 4Q01

**Version 2.0** Plan of Record for Budget/R12Q
12/04/00

**Fab 14/15:**
Capacity
- HV-7: Assumes sort equipment/hardware is compatible with HV-4. Trench Etch limited to a single machine.

**Fab 25:**
Capacity
- Removed projected support of HiP7L-SOI.
- Copper process initiated in 2Q02.
- Plated Bump schedule for 3Q02.

Defect Density Yspeed
- CS-50/H6 Yspeed modified to 0.85 in Yr2001 and 0.70 in Yr2002 – Yr2003.
- HiP7L-BULK Yspeed modified to 0.70 in Yr2002 –Yr2003

Sort Yield
- Modified NDW/Sort Yield

Wafer Transfer Price
- Added Wafer Transfer Prices for Plated Bump.

Capital Delivery
- Added Continuous Improvement, FMEA, and Technology.

**Fab 30:**
Capacity
- HiP7-BULK: Projected for 1Q02.
- HiP7-SOI: Projected for 3Q02.
- Bump Evap scheduled for 4Q01.
- Bump Plated scheduled for 3Q02.

Defect Density Yspeed
- All Yspeed changed to 0.70 except "Hammers", which were changed to 0.85.

Sort Yield
- Changed "Tackhammer" HiP7-SOI die size from 76 mm2 to 87 mm2.
- Changed "Sledgehammer" HiP7-SOI die size from 250 mm2 to 148 mm2.

**Fab8B**

Sort Yield

- Modified NDW/Sort Yield
- Separated Golem A/B.
- Added Anvil.

**0.13u Foundry #1**

Capacity

- Modified to align to present required support.

**Bump Capacity**

Capacity

- Modified to reflect no IBM support.
- Additional modifications to all support areas.

Wafer Transfer Price

- Added Fab 25 and Fab 30 Plated.

**FASL**

- Inputs for 1Q01 – 4Q01: Per FASL R6Q commitments
- Inputs for 1Q02 – 4Q03: Per FASL Business Plan JV4 200mm ver1.0

**WFG Strategic Planning**
**2001 - 2003 Indices Version 2.0 Table of Contents**
**12/04/00**

AMD

## FAB 25 3-YEAR PLAN
## FAB CAPACITY (K - 8" WAFERS)

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| CS-34 (3LM) | 2.5 | 2.5 | 2.5 | 2.5 | ***10.0*** | 2.5 | 2.5 | 2.5 | 2.5 | ***10.0*** | 1.5 | 1.5 | 1.5 | 1.5 | ***6.0*** |
| CS-44E72(5LM) | 1.0 | 1.0 | 1.0 | 1.0 | ***4.0*** | 1.0 | 1.0 | 1.0 | 1.0 | ***4.0*** | 1.0 | 1.0 | 1.0 | 1.0 | ***4.0*** |
| CS-50/H6 (6LM) | 59.0 | 59.0 | 59.0 | 59.0 | ***236.0*** | 59.0 | 54.4 | 44.4 | 36.6 | ***194.4*** | 30.9 | 30.9 | 27.1 | 24.0 | ***112.9*** |
| EE7 (3LM) | 0.5 | 0.0 | 0.0 | 0.0 | ***0.5*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| HiP7L-bulk (7LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 2.0 | 12.0 | 20.0 | ***34.0*** | 27.0 | 27.0 | 30.0 | 35.0 | ***119.0*** |
| **TOTAL** | **63.0** | **62.5** | **62.5** | **62.5** | ***250.5*** | **62.5** | **59.9** | **59.9** | **60.1** | ***242.4*** | **60.4** | **60.4** | **59.6** | **61.5** | ***241.9*** |
| **Work Weeks** | **13.0** | **13.0** | **13.0** | **13.0** | ***52.0*** | **13.0** | **13.0** | **13.0** | **13.0** | ***52.0*** | **13.0** | **13.0** | **13.0** | **13.0** | ***52.0*** |

## FAB 25 3-YEAR PLAN
## DEFECT DENSITY (Do/Sq In)

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| CS-34 (3LM) | 2.43 | 2.40 | 2.38 | 2.35 | ***2.39*** | 2.33 | 2.31 | 2.28 | 2.26 | ***2.30*** | 2.24 | 2.22 | 2.19 | 2.17 | ***2.21*** |
| CS-44E72(5LM) | 1.62 | 1.52 | 1.45 | 1.37 | ***1.49*** | 1.33 | 1.29 | 1.25 | 1.22 | ***1.27*** | 1.20 | 1.19 | 1.18 | 1.17 | ***1.19*** |
| CS-50/H6 (6LM) | 2.70 | 2.54 | 2.41 | 2.29 | ***2.49*** | 2.18 | 2.09 | 2.01 | 1.95 | ***2.06*** | 1.89 | 1.83 | 1.78 | 1.72 | ***1.81*** |
| HiP7L-bulk (7LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 0.00 | 2.70 | 2.43 | 2.19 | ***2.44*** | 1.97 | 1.85 | 1.74 | 1.63 | ***1.80*** |

## FAB 25 3-YEAR PLAN
## DEFECT DENSITY (Yspeed)

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| CS-34 (3LM) | 1.00 | 1.00 | 1.00 | 1.00 | ***1.00*** | 1.00 | 1.00 | 1.00 | 1.00 | ***1.00*** | 1.00 | 1.00 | 1.00 | 1.00 | ***1.00*** |
| CS-44E72(5LM) | 0.97 | 0.97 | 0.97 | 0.97 | ***0.97*** | 0.97 | 0.97 | 0.97 | 0.97 | ***0.97*** | 0.97 | 0.97 | 0.97 | 0.97 | ***0.97*** |
| CS-50/H6 (6LM) | 0.85 | 0.85 | 0.85 | 0.85 | ***0.85*** | 0.70 | 0.70 | 0.70 | 0.70 | ***0.70*** | 0.70 | 0.70 | 0.70 | 0.70 | ***0.70*** |
| HiP7L-bulk (7LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 0.00 | 0.70 | 0.70 | 0.70 | ***0.70*** | 0.70 | 0.70 | 0.70 | 0.70 | ***0.70*** |

## FAB 25 3-YEAR PLAN
## DEFECT DENSITY (Yprocess)

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| CS-34 (3LM) | 0.99 | 0.99 | 0.99 | 0.99 | ***0.99*** | 0.99 | 0.99 | 0.99 | 0.99 | ***0.99*** | 0.99 | 0.99 | 0.99 | 0.99 | ***0.99*** |
| CS-44E72(5LM) | 0.89 | 0.89 | 0.90 | 0.90 | ***0.90*** | 0.91 | 0.91 | 0.92 | 0.92 | ***0.92*** | 0.92 | 0.92 | 0.92 | 0.92 | ***0.92*** |
| CS-50/H6 (6LM) | 0.90 | 0.92 | 0.92 | 0.93 | ***0.92*** | 0.94 | 0.94 | 0.95 | 0.95 | ***0.95*** | 0.96 | 0.96 | 0.97 | 0.97 | ***0.97*** |
| HiP7L-bulk (7LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 0.00 | 0.79 | 0.82 | 0.84 | ***0.82*** | 0.87 | 0.89 | 0.90 | 0.91 | ***0.89*** |

## FAB 25 3-YEAR PLAN
## DEFECT DENSITY (Ytotal)

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| CS-34 (3LM) | 0.99 | 0.99 | 0.99 | 0.99 | ***0.99*** | 0.99 | 0.99 | 0.99 | 0.99 | ***0.99*** | 0.99 | 0.99 | 0.99 | 0.99 | ***0.99*** |
| CS-44E72(5LM) | 0.86 | 0.86 | 0.87 | 0.87 | ***0.87*** | 0.88 | 0.88 | 0.89 | 0.89 | ***0.89*** | 0.89 | 0.89 | 0.89 | 0.89 | ***0.89*** |
| CS-50/H6 (6LM) | 0.77 | 0.78 | 0.78 | 0.79 | ***0.78*** | 0.66 | 0.66 | 0.67 | 0.67 | ***0.67*** | 0.67 | 0.67 | 0.68 | 0.68 | ***0.68*** |
| HiP7L-bulk (7LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 0.00 | 0.55 | 0.57 | 0.59 | ***0.57*** | 0.61 | 0.62 | 0.63 | 0.64 | ***0.63*** |

## FAB 25 3-YEAR PLAN
## CYCLE TIME--FAB (DAYS)

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| CS-34 (3LM) | 70.0 | 70.0 | 70.0 | 70.0 | ***70.0*** | 70.0 | 70.0 | 70.0 | 70.0 | ***70.0*** | 70.0 | 70.0 | 70.0 | 70.0 | ***70.0*** |
| CS-44E72(5LM) | 56.0 | 63.0 | 63.0 | 63.0 | ***61.3*** | 63.0 | 63.0 | 63.0 | 63.0 | ***63.0*** | 63.0 | 63.0 | 63.0 | 63.0 | ***63.0*** |
| CS-50/H6 (6LM) | 63.0 | 63.0 | 63.0 | 63.0 | ***63.0*** | 63.0 | 63.0 | 63.0 | 63.0 | ***63.0*** | 63.0 | 63.0 | 70.0 | 70.0 | ***66.5*** |
| EE7 (3LM) | 98.0 | 0.0 | 0.0 | 0.0 | ***98.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| HiP7L-bulk (7LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 70.0 | 63.0 | 63.0 | ***65.3*** | 63.0 | 63.0 | 63.0 | 63.0 | ***63.0*** |

**Does not include either Wafer Bump or Wafer Sort Cycle Time.**

## FAB 25 3-YEAR PLAN
## PROCESS YIELD (%)

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| CS-34 (3LM) | 90.0 | 90.0 | 90.0 | 90.0 | ***90.0*** | 90.0 | 90.0 | 90.0 | 90.0 | ***90.0*** | 90.0 | 90.0 | 90.0 | 90.0 | ***90.0*** |
| CS-44E72(5LM) | 95.0 | 93.0 | 93.0 | 93.0 | ***93.5*** | 93.0 | 93.0 | 93.0 | 93.0 | ***93.0*** | 93.0 | 93.0 | 93.0 | 93.0 | ***93.0*** |
| CS-50/H6 (6LM) | 94.0 | 95.0 | 95.0 | 95.0 | ***94.8*** | 95.0 | 95.0 | 95.0 | 95.0 | ***95.0*** | 95.0 | 95.0 | 93.0 | 93.0 | ***94.0*** |
| EE7 (3LM) | 90.0 | 0.0 | 0.0 | 0.0 | ***90.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| HiP7L-bulk (7LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 85.0 | 90.0 | 91.0 | ***88.7*** | 92.0 | 93.0 | 94.0 | 95.0 | ***93.5*** |

## FAB 25 3-YEAR PLAN
## SORT YIELD (NDW - 8" WAFERS)

| CMD/TMD | Die Size Sq Mil | Die Size mm2 | Gross Die | 1Q01 | 2Q01 | 3Q01 | 4Q01 | 1Q02 | 2Q02 | 3Q02 | 4Q02 | 1Q03 | 2Q03 | 3Q03 | 4Q03 |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **CS-44E72 (5LM)** | | | | | | | | | | | | | | | |
| K6-2 | 122 | 79 | 310 | 180 | 180 | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- |
| **CS-50/H6 (6LM)** | | | | | | | | | | | | | | | |
| K7-Duron -64K (Hot) | 153 | 99 | 249 | 100 | 141 | 146 | 149 | --- | --- | --- | --- | --- | --- | --- | --- |
| K7-Duron -64K (V Hot) | 153 | 99 | 249 | --- | --- | --- | --- | 127 | 129 | 132 | 132 | 134 | 135 | 137 | 139 |
| K7-Morgan -64K (Hot) | 162 | 105 | 234 | 125 | 131 | 135 | 138 | --- | --- | --- | --- | --- | --- | --- | --- |
| K7-Morgan -64K (V Hot) | 162 | 105 | 234 | --- | --- | --- | --- | 118 | 120 | 122 | 122 | 124 | 126 | 128 | 129 |
| K7-Thunderbird -256K (Hot) | 183 | 118 | 195 | 75 | 105 | 109 | 111 | --- | --- | --- | --- | --- | --- | --- | --- |
| K7-Thunderbird -256K (V | 183 | 118 | 195 | --- | --- | --- | --- | 96 | 97 | 99 | 99 | 101 | 102 | 104 | 105 |
| **HiP7L-bulk (7LM)** | | | | | | | | | | | | | | | |
| K7-Morgan | 109 | 70 | 363 | --- | --- | --- | --- | --- | 159 | 170 | 179 | 187 | 193 | 199 | 203 |
| **EPD** | | | | | | | | | | | | | | | |
| **CS-34 (3LM)** | | | | | | | | | | | | | | | |
| 15040AR | 103 | 66 | 398 | 300 | 300 | 300 | 300 | 300 | 300 | 300 | 300 | 300 | 300 | 300 | 300 |
| 29248CQ | 65 | 42 | 638 | 550 | 550 | 550 | 550 | 550 | 550 | 550 | 550 | 550 | 550 | 550 | 550 |
| 48603AQ | 65 | 42 | 602 | 520 | 520 | 520 | 520 | 520 | 520 | 520 | 520 | 520 | 520 | 520 | 520 |
| **CS-44E72 (5LM)** | | | | | | | | | | | | | | | |
| K6-2 | 122 | 79 | 310 | 230 | 231 | 235 | 237 | 238 | 240 | 241 | 242 | 242 | 242 | 243 | 243 |
| **CS-50 (6LM)** | | | | | | | | | | | | | | | |
| K6-2+ | 115 | 74 | 316 | 192 | 195 | 197 | 199 | 200 | 202 | 203 | 204 | 204 | 205 | 206 | 207 |
| K7-Morgan | 162 | 105 | 234 | 142 | 148 | 152 | 155 | 159 | 162 | 165 | 166 | 169 | 170 | 173 | 175 |
| K7-Palomino | 197 | 127 | 192 | 108 | 113 | 117 | 120 | 123 | 125 | 129 | 129 | 132 | 133 | 136 | 137 |

## FAB 25 3-YEAR PLAN
## SORT YIELD (% - 8" WAFERS)

| CMD/TMD | Die Size Sq Mil | Die Size mm2 | Gross Die | 1Q01 | 2Q01 | 3Q01 | 4Q01 | 1Q02 | 2Q02 | 3Q02 | 4Q02 | 1Q03 | 2Q03 | 3Q03 | 4Q03 |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **CS-44E72 (5LM)** | | | | | | | | | | | | | | | |
| K6-2 | 122 | 79 | 310 | 58 | 58 | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- |
| **CS-50/H6 (6LM)** | | | | | | | | | | | | | | | |
| K7-Duron -64K (Hot) | 153 | 99 | 249 | 40 | 57 | 59 | 60 | --- | --- | --- | --- | --- | --- | --- | --- |
| K7-Duron -64K (V Hot) | 153 | 99 | 249 | --- | --- | --- | --- | 51 | 52 | 53 | 53 | 54 | 54 | 55 | 56 |
| K7-Morgan -64K (Hot) | 162 | 105 | 234 | 53 | 56 | 58 | 59 | --- | --- | --- | --- | --- | --- | --- | --- |
| K7-Morgan -64K (V Hot) | 162 | 105 | 234 | --- | --- | --- | --- | 50 | 51 | 52 | 52 | 53 | 54 | 55 | 55 |
| K7-Thunderbird -256K (Hot) | 183 | 118 | 195 | 38 | 54 | 56 | 57 | --- | --- | --- | --- | --- | --- | --- | --- |
| K7-Thunderbird -256K (V | 183 | 118 | 195 | --- | --- | --- | --- | 49 | 50 | 51 | 51 | 52 | 52 | 53 | 54 |
| **HiP7L-bulk (7LM)** | | | | | | | | | | | | | | | |
| K7-Morgan | 109 | 70 | 363 | --- | --- | --- | --- | --- | 44 | 47 | 49 | 52 | 53 | 55 | 56 |
| **EPD** | | | | | | | | | | | | | | | |
| **CS-34 (3LM)** | | | | | | | | | | | | | | | |
| 15040AR | 103 | 66 | 398 | 75 | 75 | 75 | 75 | 75 | 75 | 75 | 75 | 75 | 75 | 75 | 75 |
| 29248CQ | 65 | 42 | 638 | 86 | 86 | 86 | 86 | 86 | 86 | 86 | 86 | 86 | 86 | 86 | 86 |
| 48603AQ | 65 | 42 | 602 | 86 | 86 | 86 | 86 | 86 | 86 | 86 | 86 | 86 | 86 | 86 | 86 |
| **CS-44E72 (5LM)** | | | | | | | | | | | | | | | |
| K6-2 | 122 | 79 | 310 | 74 | 75 | 76 | 76 | 77 | 77 | 78 | 78 | 78 | 78 | 78 | 78 |
| **CS-50 (6LM)** | | | | | | | | | | | | | | | |
| K6-2+ | 115 | 74 | 316 | 61 | 62 | 62 | 63 | 63 | 64 | 64 | 65 | 65 | 65 | 65 | 66 |
| K7-Morgan | 162 | 105 | 234 | 61 | 63 | 65 | 66 | 68 | 69 | 71 | 71 | 72 | 73 | 74 | 75 |
| K7-Palomino | 197 | 127 | 192 | 56 | 59 | 61 | 63 | 64 | 65 | 67 | 67 | 69 | 69 | 71 | 71 |

## FAB 25 3-YEAR PLAN
## THREE YEAR TRANSFER PRICES (8" Wafers)

| | 2001 | 2002 | 2003 |
|---|---|---|---|
| Bump Price - Evap | 130 | 130 | 130 |
| Bump Price - Plated | --- | 500 | 300 |
| CS-34 (3LM) | 1559 | 1559 | 1559 |
| CS-44E72 (5LM) | 1800 | 1728 | 1499 |
| CS-50/H6 (6LM) | 2146 | 2060 | 1788 |
| EE7 (3LM) | 1988 | --- | --- |
| HiP7L-HD (7LM) Excl. Bump & PI | --- | 2460 | 2351 |
| Polymide | 25 | 25 | 25 |

## FAB 25 3-YEAR PLAN
## CAPITAL DELIVERY ($M)

| | 2001 | 2002 | 2003 |
|---|---|---|---|
| Continuous Improvement | 31.7 | 32.0 | 32.0 |
| Copper Conversion* | 228.8 | 112.9 | 24.8 |
| FMEA | 3.7 | 2.0 | 2.0 |
| Technology | 11.3 | --- | --- |

*** Includes facilities and C4 plating.**

## FAB 30 3-YEAR PLAN
## FAB CAPACITY (K - 8" WAFERS)

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| HIP68 (9LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 3.4 | 6.0 | 2.3 | 0.0 | ***11.8*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| HIP6L (6LM) | 26.0 | 32.6 | 38.4 | 36.8 | ***133.8*** | 40.9 | 37.3 | 22.5 | 6.7 | ***107.4*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| HIP7L - bulk (7LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 1.7 | 9.6 | 19.5 | 28.9 | ***59.7*** | 29.0 | 25.7 | 11.9 | 0.0 | ***66.6*** |
| HiP7L - SOI (9LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 10.4 | 23.3 | ***33.7*** | 34.0 | 38.1 | 53.1 | 64.9 | ***190.1*** |
| **TOTAL** | **26.0** | **32.6** | **38.4** | **36.8** | ***133.8*** | **46.0** | **52.8** | **54.7** | **58.9** | ***212.5*** | **62.9** | **63.9** | **65.0** | **64.9** | ***256.7*** |
| **Work Weeks** | **13.0** | **13.0** | **13.0** | **13.0** | ***52.0*** | **13.0** | **13.0** | **13.0** | **13.0** | ***52.0*** | **13.0** | **13.0** | **13.0** | **13.0** | ***52.0*** |

## FAB 30 3-YEAR PLAN
## DEFECT DENSITY (Do/Sq In)

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| HIP68 (9LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 1.88 | 1.69 | 1.56 | 1.45 | ***1.65*** | 1.35 | 1.29 | 1.27 | 1.24 | ***1.29*** |
| HIP6L (6LM) | 1.96 | 1.77 | 1.59 | 1.43 | ***1.69*** | 1.29 | 1.16 | 1.09 | 1.04 | ***1.15*** | 1.02 | 1.00 | 1.00 | 1.00 | ***1.01*** |
| HiP7L - bulk (7LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 2.45 | 2.21 | 2.03 | 1.89 | ***2.15*** | 1.75 | 1.68 | 1.65 | 1.62 | ***1.68*** |
| HiP7L - SOI (9LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 0.00 | 0.00 | 2.25 | 2.03 | ***2.14*** | 1.82 | 1.64 | 1.51 | 1.39 | ***1.59*** |

## FAB 30 3-YEAR PLAN
## DEFECT DENSITY (Yspeed)

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| HIP68 (9LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 0.85 | 0.85 | 0.85 | 0.85 | ***0.85*** | 0.85 | 0.85 | 0.85 | 0.85 | ***0.85*** |
| HIP6L (6LM) | 0.70 | 0.70 | 0.70 | 0.70 | ***0.70*** | 0.70 | 0.70 | 0.70 | 0.70 | ***0.70*** | 0.70 | 0.70 | 0.70 | 0.70 | ***0.70*** |
| HIP7L - bulk (7LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 0.70 | 0.70 | 0.70 | 0.70 | ***0.70*** | 0.70 | 0.70 | 0.70 | 0.70 | ***0.70*** |
| HIP7L - SOI (9LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 0.00 | 0.00 | 0.85 | 0.85 | ***0.85*** | 0.85 | 0.85 | 0.85 | 0.85 | ***0.85*** |

## FAB 30 3-YEAR PLAN
## DEFECT DENSITY (Yprocess)

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| HIP68 (9LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 0.90 | 0.90 | 0.90 | 0.90 | ***0.90*** | 0.92 | 0.92 | 0.92 | 0.92 | ***0.92*** |
| HIP6L (6LM) | 0.88 | 0.89 | 0.90 | 0.90 | ***0.89*** | 0.90 | 0.91 | 0.91 | 0.91 | ***0.91*** | 0.92 | 0.92 | 0.92 | 0.92 | ***0.92*** |
| HiP7L - bulk (7LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 0.75 | 0.85 | 0.90 | 0.90 | ***0.85*** | 0.92 | 0.92 | 0.92 | 0.92 | ***0.92*** |
| HiP7L - SOI (9LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 0.00 | 0.00 | 0.70 | 0.80 | ***0.75*** | 0.86 | 0.92 | 0.92 | 0.92 | ***0.91*** |

## FAB 30 3-YEAR PLAN
## DEFECT DENSITY (Ytotal)

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| HIP68 (9LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 0.77 | 0.77 | 0.77 | 0.77 | ***0.77*** | 0.78 | 0.78 | 0.78 | 0.78 | ***0.78*** |
| HIP6L (6LM) | 0.62 | 0.62 | 0.63 | 0.63 | ***0.63*** | 0.63 | 0.64 | 0.64 | 0.64 | ***0.64*** | 0.64 | 0.64 | 0.64 | 0.64 | ***0.64*** |
| HIP7L - bulk (7LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 0.53 | 0.60 | 0.63 | 0.63 | ***0.60*** | 0.64 | 0.64 | 0.64 | 0.64 | ***0.64*** |
| HIP7L - SOI (9LM) | 0.00 | 0.00 | 0.00 | 0.00 | ***0.00*** | 0.00 | 0.00 | 0.60 | 0.68 | ***0.64*** | 0.73 | 0.78 | 0.78 | 0.78 | ***0.77*** |

## FAB 30 3-YEAR PLAN
## CYCLE TIME--FAB (DAYS)

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| HIP68 (9LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 84.0 | 84.0 | 84.0 | 84.0 | ***84.0*** | 84.0 | 84.0 | 84.0 | 84.0 | ***84.0*** |
| HIP6L (6LM) | 63.0 | 63.0 | 63.0 | 63.0 | ***63.0*** | 63.0 | 63.0 | 63.0 | 63.0 | ***63.0*** | 63.0 | 63.0 | 63.0 | 63.0 | ***63.0*** |
| HIP7L - bulk (7LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 84.0 | 84.0 | 84.0 | 84.0 | ***84.0*** | 84.0 | 84.0 | 84.0 | 84.0 | ***84.0*** |
| HiP7L - SOI (9LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 84.0 | 84.0 | ***84.0*** | 84.0 | 84.0 | 84.0 | 84.0 | ***84.0*** |

**Does not include either Wafer Bump or Wafer Sort Cycle Time.**

## FAB 30 3-YEAR PLAN
## PROCESS YIELD (%)

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| HIP68 (9LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 82.5 | 85.0 | 87.5 | 90.0 | ***86.3*** | 90.0 | 90.0 | 90.0 | 90.0 | ***90.0*** |
| HIP6L (6LM) | 91.0 | 92.0 | 93.0 | 93.0 | ***92.3*** | 93.0 | 93.0 | 93.0 | 93.0 | ***93.0*** | 93.0 | 93.0 | 93.0 | 93.0 | ***93.0*** |
| HIP7L - bulk (7LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 85.0 | 87.5 | 90.0 | 90.0 | ***88.1*** | 90.0 | 90.0 | 90.0 | 90.0 | ***90.0*** |
| HiP7L - SOI (9LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 80.0 | 85.0 | ***82.5*** | 87.5 | 90.0 | 90.0 | 90.0 | ***89.4*** |

## FAB 30 3-YEAR PLAN
## SORT YIELD (NDW - 8" WAFERS)

| | Die Size Sq Mil | Die Size mm2 | Gross Die | 1Q01 | 2Q01 | 3Q01 | 4Q01 | 1Q02 | 2Q02 | 3Q02 | 4Q02 | 1Q03 | 2Q03 | 3Q03 | 4Q03 |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **CMD/TMD** | | | | | | | | | | | | | | | |
| **HiP68 (9LM)** | | | | | | | | | | | | | | | |
| K8-Clawhammer -256K | 245 | 158 | 152 | --- | --- | --- | --- | 79 | 83 | 85 | 88 | 91 | 93 | 93 | 94 |
| K8-Sledgehammer | 388 | 250 | 92 | --- | --- | --- | --- | 40 | 42 | 44 | 46 | 49 | 50 | 50 | 50 |
| **HiP6L (6LM)** | | | | | | | | | | | | | | | |
| K7-7309A Tb6 -256K | 187 | 121 | 204 | 118 | 99 | 104 | 106 | 107 | 111 | 112 | 113 | 115 | 115 | 115 | 115 |
| K7-Morgan -64K | 164 | 106 | 234 | --- | 113 | 117 | 120 | 123 | 127 | 129 | 130 | 131 | 132 | 132 | 132 |
| K7-Palomino -256K | 200 | 129 | 192 | 51 | 88 | 92 | 95 | 97 | 101 | 102 | 103 | 105 | 105 | 105 | 105 |
| **HiP7L (7LM)** | | | | | | | | | | | | | | | |
| K7-Morgan -64K | 109 | 70 | 363 | --- | --- | --- | --- | 152 | 176 | 190 | 192 | 199 | 201 | 202 | 202 |
| K7-Palomino -256K | 136 | 88 | 285 | --- | --- | --- | --- | 113 | 132 | 142 | 145 | 151 | 152 | 153 | 153 |
| **HiP7L (9LM)** | | | | | | | | | | | | | | | |
| K8-Clawhammer -256K | 146 | 94 | 266 | --- | --- | --- | --- | --- | --- | 124 | 145 | 157 | 172 | 175 | 178 |
| K8-Sledgehammer | 229 | 148 | 163 | --- | --- | --- | --- | --- | --- | 68 | 80 | 87 | 96 | 98 | 101 |
| K8-Tackhammer -128K | 135 | 87 | 289 | --- | --- | --- | --- | --- | --- | 137 | 159 | 173 | 189 | 192 | 195 |

## FAB 30 3-YEAR PLAN
## SORT YIELD (% - 8" WAFERS)

| | Die Size Sq Mil | Die Size mm2 | Gross Die | 1Q01 | 2Q01 | 3Q01 | 4Q01 | 1Q02 | 2Q02 | 3Q02 | 4Q02 | 1Q03 | 2Q03 | 3Q03 | 4Q03 |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **CMD/TMD** | | | | | | | | | | | | | | | |
| **HiP68 (9LM)** | | | | | | | | | | | | | | | |
| K8-Clawhammer -256K | 245 | 158 | 152 | --- | --- | --- | --- | 52 | 55 | 56 | 58 | 60 | 61 | 61 | 62 |
| K8-Sledgehammer | 388 | 250 | 92 | --- | --- | --- | --- | 43 | 46 | 48 | 50 | 53 | 54 | 54 | 54 |
| **HiP6L (6LM)** | | | | | | | | | | | | | | | |
| K7-7309A Tb6 -256K | 187 | 121 | 204 | 58 | 49 | 51 | 52 | 52 | 54 | 55 | 55 | 56 | 56 | 56 | 56 |
| K7-Morgan -64K | 164 | 106 | 234 | --- | 48 | 50 | 51 | 53 | 54 | 55 | 56 | 56 | 56 | 56 | 56 |
| K7-Palomino -256K | 200 | 129 | 192 | 27 | 46 | 48 | 49 | 51 | 53 | 53 | 54 | 55 | 55 | 55 | 55 |
| **HiP7L (7LM)** | | | | | | | | | | | | | | | |
| K7-Morgan -64K | 109 | 70 | 363 | --- | --- | --- | --- | 42 | 48 | 52 | 53 | 55 | 55 | 56 | 56 |
| K7-Palomino -256K | 136 | 88 | 285 | --- | --- | --- | --- | 40 | 46 | 50 | 51 | 53 | 53 | 54 | 54 |
| **HiP7L (9LM)** | | | | | | | | | | | | | | | |
| K8-Clawhammer -256K | 146 | 94 | 266 | --- | --- | --- | --- | --- | --- | 47 | 55 | 59 | 65 | 66 | 67 |
| K8-Sledgehammer | 229 | 148 | 163 | --- | --- | --- | --- | --- | --- | 42 | 49 | 53 | 59 | 60 | 62 |
| K8-Tackhammer -128K | 135 | 87 | 289 | --- | --- | --- | --- | --- | --- | 47 | 55 | 60 | 65 | 66 | 67 |

## FAB 30 3-YEAR PLAN
## THREE YEAR TRANSFER PRICES (8" Wafers)

| | 2001 | 2002 | 2003 |
|---|---|---|---|
| HiP68 (9LM) Excl. Bump & PI | --- | 3974 | 2625 |
| HiP6L (6LM) Excl. Bump & PI | 2555 | 2006 | 1875 |
| HiP7L - bulk (7LM) Excl. Bump & PI | --- | 2628 | 2195 |
| HiP7L - SOI (9LM) Excl. Bump & PI | --- | 3300 | 2509 |

## FAB 30 3-YEAR PLAN
## CAPITAL DELIVERY ($M)

| | 2001 | 2002 | 2003 |
|---|---|---|---|
| Equipment - C4 | 31.0 | 10.2 | 16.4 |
| Equipment - FAB | 347.4 | 175.0 | 83.1 |
| Facilities | 73.0 | 16.0 | 6.6 |
| Other | 12.4 | 9.1 | 8.3 |

AMD

# WAFER FABRICATION GROUP

# 2001-2003 WAFER OUT DEMAND/COMMITS

**Version 1.0** Based on CPG Plan 044C, not published

**Version 2.0** Plan of Record for Budget/R12Q
12/04/00

**Fab 14/15:**

- HV4: Demands exceed Commits in 1Q01 – 3Q01
- HV-7: Assumes sort equipment/hardware is compatible with HV-4. Trench Etch is limited to a single machine.

**Fab25:**

- Demands and Commits are aligned for all periods.
- Copper process initiated in 2Q02
- CPG demands based on Plan 047A

**Fab30:**

- Demands exceed Commits in 3Q01, 4Q01, and 4Q03
- HiP7-BULK: Projected for 1Q02
- HiP7-SOI: Projected for 3Q02
- CPG demands based on Plan 047A
- All capacity fully utilized.

**Fab8A:**

- Demands and Commits are aligned for all periods.

**Fab8B:**

- Demands and Commits are aligned for all periods.
- Commits exceed Capacity in Yr2003. Foundry Services will work with UMC to insure support.

**Sony:**

- Demands and Commits are aligned for all periods.

**Epson:**

- Demands and Commits are aligned for all periods.

**TSMC:**

- Demands and Commits are aligned for all periods.

**0.13u Foundry #1:**

- Based on CPG Plan 047A
- Demands and Commits are aligned for all periods.

**FASL:**

- Capacity
  - 1Q01 - 4Q01: Per FASL R6Q commitments.
  - 1Q02 - 4Q03: Per FASL Business Plan JV4 200mm ver 1.0
  - All Capacity fully utilized.
- Demands
  - Demands Source – Business Plan JV4 200mm ver 1.0
  - Demands exceed Commits in 1Q01 to 4Q03 on numerous technologies.
- New Technologies introduced as follows:
  - CS-99SB: Projected for 2Q01.
  - CS-59S: Projected for 4Q01.
  - CS-49NSD: Projected for 1Q02.
  - CS-99DB: Projected for 2Q02.
  - CS-59N: Projected for 3Q02.
  - CS-109DBH: Projected for 4Q02.

AMD

## TREE-YEAR PLAN
## FAB 14/15 WAFER OUT DEMANDS (K, 6")

| PRODUCT LINE | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **EPD TOTAL** | **7.5** | **9.3** | **8.8** | **7.6** | ***33.1*** | **7.0** | **6.5** | **6.0** | **5.1** | ***24.6*** | **4.9** | **5.0** | **4.7** | **4.3** | ***19.0*** |
| CS-21 | 0.2 | 0.1 | 0.2 | 0.1 | ***0.6*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| CS-21S | 3.3 | 4.3 | 4.1 | 3.1 | ***14.8*** | 2.6 | 2.6 | 2.5 | 2.1 | ***9.8*** | 1.8 | 1.9 | 1.8 | 1.6 | ***7.1*** |
| CS-22 | 0.4 | 0.5 | 0.5 | 0.4 | ***1.8*** | 0.2 | 0.2 | 0.2 | 0.1 | ***0.7*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| CS-23 | 3.7 | 4.3 | 4.0 | 4.0 | ***16.0*** | 4.2 | 3.7 | 3.3 | 2.9 | ***14.2*** | 3.2 | 3.1 | 2.9 | 2.7 | ***11.8*** |
| **LATTICE TOTAL** | **12.0** | **12.0** | **12.0** | **12.0** | ***48.0*** | **12.0** | **12.0** | **12.0** | **12.0** | ***48.0*** | **12.0** | **12.0** | **12.0** | **12.0** | ***48.0*** |
| EE4 | 1.7 | 1.5 | 1.0 | 1.0 | ***5.2*** | 0.8 | 0.8 | 0.8 | 0.8 | ***3.0*** | 0.8 | 0.8 | 0.8 | 0.8 | ***3.0*** |
| EE5 | 6.5 | 6.0 | 6.0 | 5.5 | ***24.0*** | 3.8 | 3.8 | 3.8 | 3.8 | ***15.0*** | 3.8 | 3.8 | 3.8 | 3.8 | ***15.0*** |
| EE65 | 3.9 | 4.5 | 5.0 | 5.5 | ***18.9*** | 7.5 | 7.5 | 7.5 | 7.5 | ***30.0*** | 7.5 | 7.5 | 7.5 | 7.5 | ***30.0*** |
| **LEGERITY TOTAL** | **35.3** | **38.7** | **41.2** | **36.6** | ***151.9*** | **37.5** | **41.7** | **44.3** | **45.3** | ***168.7*** | **46.2** | **47.8** | **49.7** | **51.2** | ***194.8*** |
| CS-21 | 5.2 | 4.7 | 3.9 | 2.8 | ***16.6*** | 2.6 | 2.4 | 2.5 | 2.5 | ***10.0*** | 2.4 | 2.4 | 2.4 | 2.4 | ***9.7*** |
| CS-21ST | 2.0 | 2.2 | 2.0 | 1.8 | ***8.1*** | 2.1 | 1.9 | 1.8 | 1.8 | ***7.5*** | 1.8 | 1.8 | 1.8 | 1.7 | ***7.1*** |
| CS-23 | 13.0 | 13.1 | 12.6 | 11.2 | ***50.0*** | 13.3 | 12.5 | 12.5 | 12.6 | ***50.9*** | 12.1 | 12.2 | 12.3 | 12.0 | ***48.5*** |
| HV4 | 13.5 | 15.6 | 17.1 | 14.6 | ***60.7*** | 10.5 | 10.7 | 10.0 | 9.8 | ***40.9*** | 9.8 | 10.0 | 10.1 | 10.2 | ***40.0*** |
| HV4+ | 1.3 | 0.9 | 1.1 | 1.3 | ***4.5*** | 4.0 | 8.9 | 11.8 | 12.6 | ***37.3*** | 13.6 | 14.6 | 15.7 | 16.9 | ***60.7*** |
| HV7 | 0.3 | 2.2 | 4.5 | 4.9 | ***12.0*** | 5.0 | 5.3 | 5.7 | 6.0 | ***22.0*** | 6.5 | 6.9 | 7.5 | 8.0 | ***28.8*** |
| **NPD TOTAL** | **13.1** | **12.9** | **12.4** | **12.1** | ***50.5*** | **9.6** | **9.5** | **8.9** | **8.9** | ***36.8*** | **7.8** | **7.8** | **7.3** | **7.3** | ***30.1*** |
| CS-21 | 0.2 | 0.2 | 0.2 | 0.2 | ***0.8*** | 0.2 | 0.2 | 0.2 | 0.2 | ***0.6*** | 0.2 | 0.2 | 0.1 | 0.1 | ***0.6*** |
| CS-21S | 12.9 | 12.7 | 12.2 | 11.9 | ***49.7*** | 9.4 | 9.4 | 8.7 | 8.7 | ***36.2*** | 7.6 | 7.6 | 7.2 | 7.2 | ***29.5*** |
| **NVD TOTAL** | **7.0** | **5.3** | **7.0** | **6.8** | ***26.1*** | **5.0** | **5.1** | **5.3** | **5.1** | ***20.5*** | **5.0** | **5.0** | **5.0** | **5.0** | ***20.0*** |
| CS-19A/AR | 0.5 | 0.7 | 0.9 | 0.7 | ***2.8*** | 0.7 | 0.0 | 0.0 | 0.0 | ***0.7*** | 0.8 | 0.8 | 0.8 | 0.8 | ***3.2*** |
| CS-19B | 1.6 | 1.6 | 1.8 | 2.1 | ***7.2*** | 2.2 | 3.0 | 2.9 | 3.0 | ***11.0*** | 4.2 | 4.2 | 4.2 | 4.2 | ***16.8*** |
| CS-19BF | 0.9 | 0.0 | 0.0 | 0.0 | ***0.9*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| CS-19BR | 4.0 | 3.0 | 4.3 | 4.0 | ***15.3*** | 2.2 | 2.2 | 2.3 | 2.1 | ***8.8*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| **TOTAL FAB** | **74.9** | **78.1** | **81.4** | **75.2** | ***309.6*** | **71.1** | **74.9** | **76.4** | **76.3** | ***298.7*** | **75.9** | **77.6** | **78.7** | **79.8** | ***311.9*** |

## THREE-YEAR PLAN
## Fab 25 WAFER OUT DEMANDS (K, 8")

| PRODUCT LINE | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **CMD/TMD TOTAL** | **59.9** | **55.5** | **58.4** | **57.8** | ***231.6*** | **57.1** | **54.3** | **53.8** | **48.5** | ***213.7*** | **26.8** | **23.1** | **27.1** | **30.9** | ***107.9*** |
| CS-44E72 (5LM) | 5.3 | 0.0 | 0.0 | 0.0 | ***5.3*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| CS-50/H6 (6LM) | 54.6 | 55.5 | 58.4 | 57.8 | ***226.3*** | 57.1 | 51.9 | 41.8 | 28.5 | ***179.3*** | 2.6 | 0.0 | 0.0 | 0.0 | ***2.6*** |
| HiP7L-bulk (7LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 2.4 | 12.0 | 20.0 | ***34.4*** | 24.2 | 23.1 | 27.1 | 30.9 | ***105.3*** |
| **EPD TOTAL** | **1.8** | **2.9** | **3.7** | **3.9** | ***12.3*** | **3.9** | **4.4** | **4.7** | **4.5** | ***17.5*** | **3.9** | **3.8** | **3.8** | **3.6** | ***15.1*** |
| CS-34 (3LM) | 1.5 | 1.6 | 2.1 | 2.0 | ***7.2*** | 1.5 | 1.6 | 1.6 | 1.5 | ***6.2*** | 1.1 | 1.2 | 1.2 | 1.1 | ***4.6*** |
| CS-44E72 (5LM) | 0.1 | 0.7 | 0.6 | 0.6 | ***2.0*** | 0.5 | 0.5 | 0.5 | 0.4 | ***1.9*** | 0.3 | 0.3 | 0.3 | 0.3 | ***1.2*** |
| CS-50/H6 (6LM) | 0.2 | 0.6 | 1.0 | 1.3 | ***3.1*** | 1.9 | 2.3 | 2.6 | 2.6 | ***9.4*** | 2.5 | 2.3 | 2.3 | 2.2 | ***9.3*** |
| **Lattice TOTAL** | **0.1** | **0.0** | **0.0** | **0.0** | ***0.1*** | **0.0** | **0.0** | **0.0** | **0.0** | ***0.0*** | **0.0** | **0.0** | **0.0** | **0.0** | ***0.0*** |
| EE7 (3LM) | 0.1 | 0.0 | 0.0 | 0.0 | ***0.1*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| **TOTAL FAB** | **61.8** | **58.4** | **62.1** | **61.7** | ***244.0*** | **61.0** | **58.7** | **58.5** | **53.0** | ***231.2*** | **30.7** | **26.9** | **30.9** | **34.5** | ***123.0*** |

## THREE-YEAR PLAN
## Fab 30 WAFER OUT DEMANDS (K, 8")

| PRODUCT LINE | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **CMD/TMD TOTAL** | **26.0** | **32.6** | **41.2** | **47.6** | ***147.4*** | **46.0** | **52.8** | **54.7** | **58.9** | ***212.5*** | **62.9** | **63.9** | **65.0** | **69.0** | ***260.8*** |
| HiP68 (9LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 3.4 | 6.0 | 2.3 | 0.0 | ***11.8*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| HiP6L (6LM) | 26.0 | 32.6 | 41.2 | 47.6 | ***147.4*** | 40.9 | 37.3 | 22.5 | 6.7 | ***107.4*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| HiP7L-bulk (7LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 1.7 | 9.6 | 19.5 | 28.9 | ***59.7*** | 29.0 | 25.7 | 11.9 | 0.0 | ***66.6*** |
| HiP7L-SOI (9LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 10.4 | 23.3 | ***33.7*** | 34.0 | 38.1 | 53.1 | 69.0 | ***194.2*** |
| **TOTAL FAB** | **26.0** | **32.6** | **41.2** | **47.6** | ***147.4*** | **46.0** | **52.8** | **54.7** | **58.9** | ***212.5*** | **62.9** | **63.9** | **65.0** | **69.0** | ***260.8*** |

## THREE-YEAR PLAN
## FASL 1 SORT OUT DEMANDS (K, 8")
## AMD ONLY

| PRODUCT LINE | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **NVD TOTAL** | **45.0** | **44.9** | **47.3** | **48.6** | ***185.8*** | **51.0** | **48.9** | **50.9** | **52.1** | ***202.9*** | **45.7** | **46.0** | **49.2** | **49.4** | ***190.3*** |
| CS-39S | 45.0 | 44.9 | 47.3 | 48.6 | ***185.8*** | 51.0 | 48.9 | 50.9 | 52.1 | ***202.9*** | 45.7 | 43.5 | 43.5 | 40.3 | ***173.0*** |
| CS-99DB | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 2.5 | 5.7 | 9.1 | ***17.3*** |
| **TOTAL FAB** | **45.0** | **44.9** | **47.3** | **48.6** | ***185.8*** | **51.0** | **48.9** | **50.9** | **52.1** | ***202.9*** | **45.7** | **46.0** | **49.2** | **49.4** | ***190.3*** |

## THREE-YEAR PLAN
## FASL 2 SORT OUT DEMANDS (K, 8")
## AMD ONLY

| PRODUCT LINE | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **NVD TOTAL** | **45.5** | **58.9** | **71.9** | **79.6** | ***255.9*** | **85.5** | **91.2** | **60.7** | **46.2** | ***283.6*** | **49.7** | **47.7** | **46.2** | **45.8** | ***189.4*** |
| CS-109DBH | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 2.2 | 11.9 | 17.5 | 21.4 | ***53.0*** |
| CS-49N/NS | 11.7 | 14.9 | 16.7 | 20.3 | ***63.6*** | 23.3 | 22.9 | 5.9 | 6.0 | ***58.1*** | 6.8 | 6.5 | 0.0 | 0.0 | ***13.3*** |
| CS-49NSD | 0.0 | 0.0 | 2.8 | 4.5 | ***7.3*** | 4.9 | 6.9 | 0.6 | 0.6 | ***13.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| CS-99S/HS | 33.8 | 43.8 | 42.3 | 44.6 | ***164.5*** | 44.8 | 27.2 | 25.5 | 18.3 | ***115.8*** | 14.0 | 3.8 | 0.0 | 0.0 | ***17.8*** |
| CS-99DB | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 32.9 | 27.3 | 19.9 | ***80.1*** | 25.3 | 25.5 | 28.7 | 24.4 | ***103.9*** |
| CS-99SB | 0.0 | 0.2 | 10.1 | 10.2 | ***20.5*** | 12.5 | 1.3 | 1.4 | 1.4 | ***16.6*** | 1.4 | 0.0 | 0.0 | 0.0 | ***1.4*** |
| **TOTAL FAB** | **45.5** | **58.9** | **71.9** | **79.6** | ***255.9*** | **85.5** | **91.2** | **60.7** | **46.2** | ***283.6*** | **49.7** | **47.7** | **46.2** | **45.8** | ***189.4*** |

## THREE-YEAR PLAN
## FASL 3 SORT OUT DEMANDS (K, 8")
## AMD ONLY

| PRODUCT LINE | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **NVD TOTAL** | **0.0** | **0.0** | **0.0** | **10.8** | ***10.8*** | **10.8** | **22.7** | **55.1** | **95.3** | ***183.9*** | **93.8** | **104.1** | **100.8** | **114.1** | ***412.8*** |
| CS-109DBH | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 0.0 | 13.1 | ***13.1*** | 7.1 | 14.5 | 11.2 | 15.8 | ***48.6*** |
| CS-59N | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 9.1 | 28.9 | 50.6 | ***88.6*** | 54.7 | 68.3 | 69.7 | 83.4 | ***276.1*** |
| CS-59S | 0.0 | 0.0 | 0.0 | 10.8 | ***10.8*** | 10.8 | 13.6 | 26.2 | 31.6 | ***82.2*** | 32.0 | 21.3 | 19.9 | 14.9 | ***88.1*** |
| **TOTAL FAB** | **0.0** | **0.0** | **0.0** | **10.8** | ***10.8*** | **10.8** | **22.7** | **55.1** | **95.3** | ***183.9*** | **93.8** | **104.1** | **100.8** | **114.1** | ***412.8*** |

## THREE-YEAR PLAN
## FASL 4 SORT OUT DEMANDS (K, 8")
## AMD ONLY

| PRODUCT LINE | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **NVD TOTAL** | **0.0** | **0.0** | **0.0** | **0.0** | ***0.0*** | **0.0** | **0.0** | **0.0** | **4.2** | ***4.2*** | **7.9** | **20.2** | **30.8** | **41.6** | ***100.5*** |
| CS-109DBH | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 0.0 | 4.2 | ***4.2*** | 7.9 | 20.2 | 30.8 | 41.6 | ***100.5*** |
| **TOTAL FAB** | **0.0** | **0.0** | **0.0** | **0.0** | ***0.0*** | **0.0** | **0.0** | **0.0** | **4.2** | ***4.2*** | **7.9** | **20.2** | **30.8** | **41.6** | ***100.5*** |

## THREE-YEAR PLAN
## Fab 25 WAFER OUT COMMITS (K, 8")

| PRODUCT LINE | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **CMD/TMD TOTAL** | **59.9** | **55.5** | **58.4** | **57.8** | ***231.6*** | **57.1** | **54.3** | **53.8** | **48.5** | ***213.7*** | **26.8** | **23.1** | **27.1** | **30.9** | ***107.9*** |
| CS-44E72 (5LM) | 5.3 | 0.0 | 0.0 | 0.0 | ***5.3*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| CS-50/H6 (6LM) | 54.6 | 55.5 | 58.4 | 57.8 | ***226.3*** | 57.1 | 51.9 | 41.8 | 28.5 | ***179.3*** | 2.6 | 0.0 | 0.0 | 0.0 | ***2.6*** |
| HiP7L-bulk (7LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 2.4 | 12.0 | 20.0 | ***34.4*** | 24.2 | 23.1 | 27.1 | 30.9 | ***105.3*** |
| **EPD TOTAL** | **1.8** | **2.9** | **3.7** | **3.9** | ***12.3*** | **3.9** | **4.4** | **4.7** | **4.5** | ***17.5*** | **3.9** | **3.8** | **3.8** | **3.6** | ***15.1*** |
| CS-34 (3LM) | 1.5 | 1.6 | 2.1 | 2.0 | ***7.2*** | 1.5 | 1.6 | 1.6 | 1.5 | ***6.2*** | 1.1 | 1.2 | 1.2 | 1.1 | ***4.6*** |
| CS-44E72 (5LM) | 0.1 | 0.7 | 0.6 | 0.6 | ***2.0*** | 0.5 | 0.5 | 0.5 | 0.4 | ***1.9*** | 0.3 | 0.3 | 0.3 | 0.3 | ***1.2*** |
| CS-50/H6 (6LM) | 0.2 | 0.6 | 1.0 | 1.3 | ***3.1*** | 1.9 | 2.3 | 2.6 | 2.6 | ***9.4*** | 2.5 | 2.3 | 2.3 | 2.2 | ***9.3*** |
| **Lattice TOTAL** | **0.1** | **0.0** | **0.0** | **0.0** | ***0.1*** | **0.0** | **0.0** | **0.0** | **0.0** | ***0.0*** | **0.0** | **0.0** | **0.0** | **0.0** | ***0.0*** |
| EE7 (3LM) | 0.1 | 0.0 | 0.0 | 0.0 | ***0.1*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| **TOTAL FAB** | **61.8** | **58.4** | **62.1** | **61.7** | ***244.0*** | **61.0** | **58.7** | **58.5** | **53.0** | ***231.2*** | **30.7** | **26.9** | **30.9** | **34.5** | ***123.0*** |

## THREE-YEAR PLAN
## Fab 25 WAFER OUT COMMITS (K, 8")

| TECHNOLOGY | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| CS-34 (3LM) | 1.5 | 1.6 | 2.1 | 2.0 | ***7.2*** | 1.5 | 1.6 | 1.6 | 1.5 | ***6.2*** | 1.1 | 1.2 | 1.2 | 1.1 | ***4.6*** |
| CS-44E72 (5LM) | 5.4 | 0.7 | 0.6 | 0.6 | ***7.3*** | 0.5 | 0.5 | 0.5 | 0.4 | ***1.9*** | 0.3 | 0.3 | 0.3 | 0.3 | ***1.2*** |
| CS-50/H6 (6LM) | 54.8 | 56.1 | 59.4 | 59.1 | ***229.4*** | 59.0 | 54.2 | 44.4 | 31.1 | ***188.7*** | 5.1 | 2.3 | 2.3 | 2.2 | ***11.9*** |
| EE7 (3LM) | 0.1 | 0.0 | 0.0 | 0.0 | ***0.1*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| HiP7L-bulk (7LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 2.4 | 12.0 | 20.0 | ***34.4*** | 24.2 | 23.1 | 27.1 | 30.9 | ***105.3*** |
| **TOTAL FAB** | **61.8** | **58.4** | **62.1** | **61.7** | ***244.0*** | **61.0** | **58.7** | **58.5** | **53.0** | ***231.2*** | **30.7** | **26.9** | **30.9** | **34.5** | ***123.0*** |

## THREE-YEAR PLAN
## FAB 25 WAFER OUT CAPACITY (K, 8")

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| CS-34 (3LM) | 2.5 | 2.5 | 2.5 | 2.5 | ***10.0*** | 2.5 | 2.5 | 2.5 | 2.5 | ***10.0*** | 1.5 | 1.5 | 1.5 | 1.5 | ***6.0*** |
| CS-44E72(5LM) | 1.0 | 1.0 | 1.0 | 1.0 | ***4.0*** | 1.0 | 1.0 | 1.0 | 1.0 | ***4.0*** | 1.0 | 1.0 | 1.0 | 1.0 | ***4.0*** |
| CS-50/H6 (6LM) | 59.0 | 59.0 | 59.0 | 59.0 | ***236.0*** | 59.0 | 54.4 | 44.4 | 36.6 | ***194.4*** | 30.9 | 30.9 | 27.1 | 24.0 | ***112.9*** |
| EE7 (3LM) | 0.5 | 0.0 | 0.0 | 0.0 | ***0.5*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| HiP7L-bulk (7LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 2.0 | 12.0 | 20.0 | ***34.0*** | 27.0 | 27.0 | 30.0 | 35.0 | ***119.0*** |
| **TOTAL** | **63.0** | **62.5** | **62.5** | **62.5** | ***250.5*** | **62.5** | **59.9** | **59.9** | **60.1** | ***242.4*** | **60.4** | **60.4** | **59.6** | **61.5** | ***241.9*** |
| **Work Weeks** | **13.0** | **13.0** | **13.0** | **13.0** | ***52.0*** | **13.0** | **13.0** | **13.0** | **13.0** | ***52.0*** | **13.0** | **13.0** | **13.0** | **13.0** | ***52.0*** |

## THREE-YEAR PLAN
## Fab 30 WAFER OUT COMMITS (K, 8")

| PRODUCT LINE | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **CMD/TMD TOTAL** | **26.0** | **32.6** | **38.4** | **36.8** | ***133.8*** | **46.0** | **52.8** | **54.7** | **58.9** | ***212.5*** | **62.9** | **63.9** | **65.0** | **64.9** | ***256.7*** |
| HiP68 (9LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 3.4 | 6.0 | 2.3 | 0.0 | ***11.8*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| HiP6L (6LM) | 26.0 | 32.6 | 38.4 | 36.8 | ***133.8*** | 40.9 | 37.3 | 22.5 | 6.7 | ***107.4*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| HiP7L-bulk (7LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 1.7 | 9.6 | 19.5 | 28.9 | ***59.7*** | 29.0 | 25.7 | 11.9 | 0.0 | ***66.6*** |
| HiP7L-SOI (9LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 10.4 | 23.3 | ***33.7*** | 34.0 | 38.1 | 53.1 | 64.9 | ***190.1*** |
| **TOTAL FAB** | **26.0** | **32.6** | **38.4** | **36.8** | ***133.8*** | **46.0** | **52.8** | **54.7** | **58.9** | ***212.5*** | **62.9** | **63.9** | **65.0** | **64.9** | ***256.7*** |

## THREE-YEAR PLAN
## Fab 30 WAFER OUT COMMITS (K, 8")

| TECHNOLOGY | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| HiP68 (9LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 3.4 | 6.0 | 2.3 | 0.0 | ***11.8*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| HiP6L (6LM) | 26.0 | 32.6 | 38.4 | 36.8 | ***133.8*** | 40.9 | 37.3 | 22.5 | 6.7 | ***107.4*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| HiP7L-bulk (7LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 1.7 | 9.6 | 19.5 | 28.9 | ***59.7*** | 29.0 | 25.7 | 11.9 | 0.0 | ***66.6*** |
| HiP7L-SOI (9LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 10.4 | 23.3 | ***33.7*** | 34.0 | 38.1 | 53.1 | 64.9 | ***190.1*** |
| **TOTAL FAB** | **26.0** | **32.6** | **38.4** | **36.8** | ***133.8*** | **46.0** | **52.8** | **54.7** | **58.9** | ***212.5*** | **62.9** | **63.9** | **65.0** | **64.9** | ***256.7*** |

## THREE-YEAR PLAN
## FAB 30 WAFER OUT CAPACITY (K, 8")

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | *2001* | 1Q02 | 2Q02 | 3Q02 | 4Q02 | *2002* | 1Q03 | 2Q03 | 3Q03 | 4Q03 | *2003* |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| HIP68 (9LM) | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 3.4 | 6.0 | 2.3 | 0.0 | ***11.8*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| HIP6L (6LM) | 26.0 | 32.6 | 38.4 | 36.8 | ***133.8*** | 40.9 | 37.3 | 22.5 | 6.7 | ***107.4*** | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** |
| 7L - bulk | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 1.7 | 9.6 | 19.5 | 28.9 | ***59.7*** | 29.0 | 25.7 | 11.9 | 0.0 | ***66.6*** |
| HiP7L - SOI | 0.0 | 0.0 | 0.0 | 0.0 | ***0.0*** | 0.0 | 0.0 | 10.4 | 23.3 | ***33.7*** | 34.0 | 38.1 | 53.1 | 64.9 | ***190.1*** |
| **TOTAL** | **26.0** | **32.6** | **38.4** | **36.8** | ***133.8*** | **46.0** | **52.8** | **54.7** | **58.9** | ***212.5*** | **62.9** | **63.9** | **65.0** | **64.9** | ***256.7*** |
| **Work Weeks** | **13.0** | **13.0** | **13.0** | **13.0** | ***52.0*** | **13.0** | **13.0** | **13.0** | **13.0** | ***52.0*** | **13.0** | **13.0** | **13.0** | **13.0** | ***52.0*** |

## THREE-YEAR PLAN
## WAFER FABRICATION GROUP COMMITS VS. CAPACITIES (K, 8")
## BY FAB

| | 1Q02 | | | 2Q02 | | | 3Q02 | | | 4Q02 | | | 2002 | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | COM | CAP | DEL | COM | CAP | DEL | COM | CAP | DEL | COM | CAP | DEL | COM | CAP | DEL |
| 0.13u Fdry #1 - (BULK) | 6.0 | 6.0 | 0.0 | 3.8 | 3.8 | 0.0 | 5.9 | 5.9 | 0.0 | 1.1 | 1.1 | 0.0 | 16.9 | 16.9 | 0.0 |
| EPSON | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| FAB 14/15 | 39.9 | 46.2 | 6.3 | 42.1 | 46.2 | 4.2 | 42.9 | 46.2 | 3.3 | 42.9 | 46.2 | 3.4 | 167.8 | 184.9 | 17.1 |
| Fab 25 | 61.0 | 62.5 | 1.5 | 58.7 | 59.9 | 1.2 | 58.5 | 59.9 | 1.4 | 53.0 | 60.1 | 7.1 | 231.2 | 242.4 | 11.2 |
| Fab 30 | 46.0 | 46.0 | 0.0 | 52.8 | 52.8 | 0.0 | 54.7 | 54.7 | 0.0 | 58.9 | 58.9 | 0.0 | 212.5 | 212.5 | 0.0 |
| Fab8A | 1.2 | 2.0 | 0.8 | 1.2 | 2.0 | 0.8 | 1.2 | 2.0 | 0.8 | 1.2 | 2.0 | 0.8 | 4.8 | 8.0 | 3.2 |
| Fab8B | 8.4 | 19.1 | 10.7 | 7.7 | 19.1 | 11.4 | 9.1 | 19.1 | 10.0 | 13.0 | 19.1 | 6.1 | 38.2 | 76.4 | 38.2 |
| FASL - GMD | 27.0 | 27.0 | 0.0 | 25.8 | 25.8 | 0.0 | 27.8 | 27.8 | 0.0 | 36.0 | 36.0 | 0.0 | 116.6 | 116.6 | 0.0 |
| FASL - IWATE | 15.1 | 15.1 | 0.0 | 14.5 | 14.5 | 0.0 | 13.4 | 13.4 | 0.0 | 14.0 | 14.0 | 0.0 | 57.0 | 57.0 | 0.0 |
| FASL 1 | 48.0 | 48.0 | 0.0 | 45.6 | 45.6 | 0.0 | 45.6 | 45.6 | 0.0 | 45.6 | 45.6 | 0.0 | 184.8 | 184.8 | 0.0 |
| FASL 2 | 35.7 | 35.7 | 0.0 | 36.9 | 36.9 | 0.0 | 37.7 | 37.7 | 0.0 | 40.4 | 40.4 | 0.0 | 150.6 | 150.6 | 0.0 |
| FASL 3 | 0.0 | 0.0 | 0.0 | 12.9 | 12.9 | 0.0 | 26.3 | 26.3 | 0.0 | 36.2 | 36.2 | 0.0 | 75.4 | 75.4 | 0.0 |
| FASL 4 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.5 | 0.5 | 0.0 | 0.5 | 0.5 | 0.0 |
| SONY | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| TSMC | 0.1 | 0.2 | 0.1 | 0.1 | 0.2 | 0.1 | 0.1 | 0.2 | 0.1 | 0.1 | 0.2 | 0.1 | 0.5 | 0.8 | 0.3 |
| **TOTAL FAB** | **288.4** | **307.8** | **19.3** | **302.2** | **319.8** | **17.6** | **323.3** | **338.9** | **15.6** | **342.9** | **360.3** | **17.4** | **1256.8** | **1326.8** | **70.0** |

## THREE-YEAR PLAN
## WAFER FABRICATION GROUP COMMITS VS. CAPACITIES (K, 8")
## BY FAB

| | 1Q03 | | | 2Q03 | | | 3Q03 | | | 4Q03 | | | 2003 | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | COM | CAP | DEL | COM | CAP | DEL | COM | CAP | DEL | COM | CAP | DEL | COM | CAP | DEL |
| 0.13u Fdry #1 - (BULK) | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| EPSON | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| FA[illegible]5 | 42.6 | 46.2 | 3.6 | 43.6 | 46.2 | 2.6 | 44.2 | 46.2 | 2.0 | 44.8 | 46.2 | 1.4 | 175.2 | 184.9 | 9.7 |
| Fab[illegible] | 30.7 | 60.4 | 29.7 | 26.9 | 60.4 | 33.5 | 30.9 | 59.6 | 28.7 | 34.5 | 61.5 | 27.0 | 123.0 | 241.9 | 118.9 |
| Fab 30 | 62.9 | 62.9 | 0.0 | 63.9 | 63.9 | 0.0 | 65.0 | 65.0 | 0.0 | 64.9 | 64.9 | 0.0 | 256.7 | 256.7 | 0.0 |
| Fab8A | 1.1 | 2.0 | 0.9 | 1.1 | 2.0 | 0.9 | 1.0 | 2.0 | 1.0 | 1.0 | 2.0 | 1.0 | 4.2 | 8.0 | 3.8 |
| Fab8B | 19.5 | 19.1 | -0.4 | 25.9 | 19.1 | -6.8 | 31.8 | 19.1 | -12.7 | 41.4 | 19.1 | -22.3 | 118.5 | 76.4 | -42.1 |
| FASL - GMD | 38.5 | 38.5 | 0.0 | 41.2 | 41.2 | 0.0 | 44.1 | 44.1 | 0.0 | 46.7 | 46.7 | 0.0 | 170.5 | 170.5 | 0.0 |
| FASL - IWATE | 17.1 | 17.1 | 0.0 | 17.9 | 17.9 | 0.0 | 18.9 | 18.9 | 0.0 | 18.9 | 18.9 | 0.0 | 72.6 | 72.6 | 0.0 |
| FASL 1 | 39.0 | 39.0 | 0.0 | 41.2 | 41.2 | 0.0 | 44.8 | 44.8 | 0.0 | 44.9 | 44.9 | 0.0 | 169.8 | 169.8 | 0.0 |
| FASL 2 | 43.0 | 43.0 | 0.0 | 42.3 | 42.3 | 0.0 | 42.1 | 42.1 | 0.0 | 41.6 | 41.6 | 0.0 | 168.9 | 168.9 | 0.0 |
| FASL 3 | 46.2 | 46.2 | 0.0 | 48.5 | 48.5 | 0.0 | 51.9 | 51.9 | 0.0 | 52.3 | 52.3 | 0.0 | 198.8 | 198.8 | 0.0 |
| FASL 4 | 5.5 | 5.5 | 0.0 | 16.0 | 16.0 | 0.0 | 28.0 | 28.0 | 0.0 | 37.8 | 37.8 | 0.0 | 87.3 | 87.3 | 0.0 |
| SONY | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| TSMC | 0.1 | 0.2 | 0.1 | 0.1 | 0.2 | 0.1 | 0.1 | 0.2 | 0.1 | 0.1 | 0.2 | 0.1 | 0.4 | 0.8 | 0.4 |
| **TOTAL FAB** | **346.1** | **380.0** | **34.0** | **368.4** | **398.8** | **30.4** | **402.6** | **421.7** | **19.1** | **428.8** | **436.0** | **7.2** | **1545.8** | **1636.5** | **90.7** |

## THREE-YEAR PLAN
## WAFER FABRICATION GROUP COMMITS (K, 8")
### BY FAB

| FAB/FOUNDRY | 1Q01 | 2Q01 | 3Q01 | 4Q01 | 2001 | 1Q02 | 2Q02 | 3Q02 | 4Q02 | 2002 | 1Q03 | 2Q03 | 3Q03 | 4Q03 | 2003 |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 0.13u Fdry #1 - (BULK) | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 6.0 | 3.8 | 5.9 | 1.1 | 16.9 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| EPSON | 0.1 | 0.1 | 0.1 | 0.1 | 0.5 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| FAB 14/15 | 41.6 | 41.8 | 43.1 | 42.3 | 168.7 | 39.9 | 42.1 | 42.9 | 42.9 | 167.8 | 42.6 | 43.6 | 44.2 | 44.8 | 175.2 |
| Fab 25 | 61.8 | 58.4 | 62.1 | 61.7 | 244.0 | 61.0 | 58.7 | 58.5 | 53.0 | 231.2 | 30.7 | 26.9 | 30.9 | 34.5 | 123.0 |
| Fab 30 | 26.0 | 32.6 | 38.4 | 36.8 | 133.8 | 46.0 | 52.8 | 54.7 | 58.9 | 212.5 | 62.9 | 63.9 | 65.0 | 64.9 | 256.7 |
| Fab8A | 0.9 | 1.3 | 1.4 | 1.4 | 5.0 | 1.2 | 1.2 | 1.2 | 1.2 | 4.8 | 1.1 | 1.1 | 1.0 | 1.0 | 4.2 |
| Fab8B | 9.7 | 11.9 | 10.7 | 7.7 | 40.0 | 8.4 | 7.7 | 9.1 | 13.0 | 38.2 | 19.5 | 25.9 | 31.8 | 41.4 | 118.5 |
| FASL - GMD | 8.7 | 10.7 | 14.3 | 24.2 | 57.9 | 27.0 | 25.8 | 27.8 | 36.0 | 116.6 | 38.5 | 41.2 | 44.1 | 46.7 | 170.5 |
| FASL - IWATE | 17.0 | 16.3 | 16.6 | 17.6 | 67.5 | 15.1 | 14.5 | 13.4 | 14.0 | 57.0 | 17.1 | 17.9 | 18.9 | 18.9 | 72.6 |
| FASL 1 | 45.0 | 44.7 | 47.3 | 48.0 | 185.0 | 48.0 | 45.6 | 45.6 | 45.6 | 184.8 | 39.0 | 41.2 | 44.8 | 44.9 | 169.8 |
| FASL 2 | 27.9 | 31.1 | 33.6 | 35.6 | 128.1 | 35.7 | 36.9 | 37.7 | 40.4 | 150.6 | 43.0 | 42.3 | 42.1 | 41.6 | 168.9 |
| FASL 3 | 0.0 | 0.0 | 0.0 | 0.5 | 0.5 | 0.0 | 12.9 | 26.3 | 36.2 | 75.4 | 46.2 | 48.5 | 51.9 | 52.3 | 198.8 |
| FASL 4 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.5 | 0.5 | 5.5 | 16.0 | 28.0 | 37.8 | 87.3 |
| SONY | 0.6 | 0.4 | 0.2 | 0.1 | 1.3 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| TSMC | 0.0 | 0.1 | 0.1 | 0.1 | 0.3 | 0.1 | 0.1 | 0.1 | 0.1 | 0.5 | 0.1 | 0.1 | 0.1 | 0.1 | 0.4 |
| **TOTAL FAB** | **239.2** | **249.5** | **267.8** | **276.1** | **1032.** | **288.4** | **302.2** | **323.3** | **342.9** | **1256.** | **346.1** | **368.4** | **402.6** | **428.8** | **1545.8** |

## THREE-YEAR PLAN
## WAFER FABRICATION GROUP COMMITS (K, 8")
## BY GEOMETRY

| MICRON SIZE | 1Q01 | 2Q01 | 3Q01 | 4Q01 | 2001 | 1Q02 | 2Q02 | 3Q02 | 4Q02 | 2002 | 1Q03 | 2Q03 | 3Q03 | 4Q03 | 2003 |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **>0.25u TOTAL** | **0.0** | **0.1** | **0.1** | **0.1** | **0.3** | **0.1** | **0.1** | **0.1** | **0.1** | **0.5** | **0.1** | **0.1** | **0.1** | **0.1** | **0.4** |
| 0.35u 2P3M | 0.0 | 0.1 | 0.1 | 0.1 | 0.3 | 0.1 | 0.1 | 0.1 | 0.1 | 0.5 | 0.1 | 0.1 | 0.1 | 0.1 | 0.4 |
| **>0.5u TOTAL** | **42.5** | **42.7** | **43.8** | **43.0** | **171.9** | **40.4** | **42.5** | **43.4** | **43.3** | **169.5** | **43.1** | **44.0** | **44.6** | **45.2** | **176.9** |
| 0.32u 1P3M | 0.2 | 0.3 | 0.4 | 0.5 | 1.4 | 0.4 | 0.4 | 0.4 | 0.4 | 1.7 | 0.4 | 0.4 | 0.4 | 0.4 | 1.7 |
| CS-19A/AR | 0.3 | 0.4 | 0.5 | 0.4 | 1.6 | 0.4 | 0.0 | 0.0 | 0.0 | 0.4 | 0.5 | 0.5 | 0.4 | 0.4 | 1.8 |
| CS-19B | 0.9 | 0.9 | 1.0 | 1.2 | 4.0 | 1.2 | 1.7 | 1.7 | 1.7 | 6.2 | 2.3 | 2.3 | 2.4 | 2.4 | 9.4 |
| CS-19BF | 0.5 | 0.0 | 0.0 | 0.0 | 0.5 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| CS-19BR | 2.3 | 1.7 | 2.4 | 2.3 | 8.6 | 1.2 | 1.2 | 1.3 | 1.2 | 4.9 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| CS-21 | 3.1 | 2.9 | 2.4 | 1.7 | 10.1 | 1.6 | 1.5 | 1.5 | 1.5 | 6.0 | 1.4 | 1.4 | 1.4 | 1.4 | 5.8 |
| CS-21S | 9.1 | 9.5 | 9.1 | 8.4 | 36.2 | 6.8 | 6.7 | 6.3 | 6.1 | 25.8 | 5.3 | 5.4 | 5.0 | 4.9 | 20.6 |
| CS-21ST | 1.2 | 1.3 | 1.1 | 1.0 | 4.6 | 1.2 | 1.0 | 1.0 | 1.0 | 4.2 | 1.0 | 1.0 | 1.0 | 1.0 | 4.0 |
| CS-22 | 0.2 | 0.3 | 0.3 | 0.2 | 1.0 | 0.1 | 0.1 | 0.1 | 0.0 | 0.4 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| CS-23 | 9.4 | 9.8 | 9.4 | 8.6 | 37.1 | 9.9 | 9.1 | 8.9 | 8.7 | 36.6 | 8.6 | 8.6 | 8.5 | 8.2 | 33.9 |
| EE4 | 0.9 | 0.8 | 0.6 | 0.6 | 2.9 | 0.4 | 0.4 | 0.4 | 0.4 | 1.7 | 0.4 | 0.4 | 0.4 | 0.4 | 1.7 |
| EE5 | 3.7 | 3.4 | 3.4 | 3.1 | 13.5 | 2.1 | 2.1 | 2.1 | 2.1 | 8.4 | 2.1 | 2.1 | 2.1 | 2.1 | 8.4 |
| EE65 | 2.2 | 2.5 | 2.8 | 3.1 | 10.6 | 4.2 | 4.2 | 4.2 | 4.2 | 16.9 | 4.2 | 4.2 | 4.2 | 4.2 | 16.9 |
| HV4 | 7.2 | 6.7 | 6.9 | 8.2 | 28.9 | 5.9 | 6.0 | 5.6 | 5.5 | 23.0 | 5.5 | 5.6 | 5.7 | 5.7 | 22.5 |
| HV4+ | 0.7 | 0.5 | 0.6 | 0.7 | 2.6 | 2.2 | 5.0 | 6.6 | 7.1 | 21.0 | 7.6 | 8.2 | 8.8 | 9.5 | 34.1 |
| HV7 | 0.2 | 1.3 | 2.5 | 2.8 | 6.7 | 2.8 | 3.0 | 3.2 | 3.4 | 12.4 | 3.6 | 3.9 | 4.2 | 4.5 | 16.2 |
| IMOX2 | 0.3 | 0.2 | 0.0 | 0.0 | 0.5 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| IMOX2S | 0.2 | 0.1 | 0.0 | 0.0 | 0.3 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| LS | 0.0 | 0.1 | 0.2 | 0.1 | 0.5 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| SMS12-6" | 0.0 | 0.0 | 0.0 | 0.0 | 0.2 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| SMSDL-5" | 0.1 | 0.1 | 0.1 | 0.1 | 0.3 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| **0.13 TOTAL** | **0.0** | **0.0** | **0.0** | **0.0** | **0.0** | **6.0** | **3.8** | **5.9** | **1.1** | **16.9** | **0.0** | **0.0** | **0.0** | **0.0** | **0.0** |
| 0.13u Technology | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 6.0 | 3.8 | 5.9 | 1.1 | 16.9 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| **0.13u TOTAL** | **0.0** | **0.0** | **0.0** | **0.0** | **0.0** | **1.7** | **12.0** | **41.9** | **72.2** | **127.8** | **87.1** | **87.0** | **92.1** | **95.8** | **362.0** |
| HiP7L-bulk (7LM) | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 1.7 | 12.0 | 31.5 | 48.9 | 94.1 | 53.2 | 48.8 | 39.0 | 30.9 | 171.9 |
| HiP7L-SOI (9LM) | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 10.4 | 23.3 | 33.7 | 34.0 | 38.1 | 53.1 | 64.9 | 190.1 |
| **0.18u TOTAL** | **80.8** | **88.7** | **97.8** | **96.6** | **363.9** | **104.2** | **112.0** | **99.0** | **81.0** | **396.2** | **70.5** | **94.3** | **120.4** | **141.4** | **426.6** |
| 0.18u 1P5M | 0.0 | 0.0 | 0.0 | 0.2 | 0.2 | 0.8 | 1.5 | 2.0 | 2.2 | 6.4 | 1.8 | 1.3 | 0.8 | 0.9 | 4.8 |
| 0.18u 1P6M | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 1.2 | 3.9 | 5.2 | 9.3 | 15.1 | 20.1 | 27.4 | 71.8 |
| 0.18u 5LM | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.1 | 0.1 | 0.4 | 0.2 | 0.2 | 0.2 | 0.2 | 0.9 |
| 0.18u 6LM | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.1 | 0.1 | 0.2 | 0.2 | 0.6 | 0.7 | 0.7 | 1.2 | 1.2 | 3.8 |
| CS-109DBH | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 2.3 | 2.3 | 13.3 | 42.5 | 59.5 | 78.8 | 194.1 |
| CS-50/H6 (6LM) | 54.8 | 56.1 | 59.4 | 59.1 | 229.4 | 59.0 | 54.2 | 44.4 | 31.1 | 188.7 | 5.1 | 2.3 | 2.3 | 2.2 | 11.9 |
| CS-59N | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 1.4 | 3.3 | 4.7 | 8.1 | 10.9 | 16.4 | 15.8 | 51.2 |
| CS-59S | 0.0 | 0.0 | 0.0 | 0.5 | 0.5 | 0.0 | 12.9 | 24.9 | 31.2 | 69.0 | 32.0 | 21.3 | 19.9 | 14.9 | 88.1 |
| HiP68 (9LM) | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 3.4 | 6.0 | 2.3 | 0.0 | 11.8 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| HiP6L (6LM) | 26.0 | 32.6 | 38.4 | 36.8 | 133.8 | 40.9 | 37.3 | 22.5 | 6.7 | 107.4 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| **0.22u TOTAL** | **52.8** | **57.3** | **63.1** | **75.1** | **248.3** | **72.7** | **68.0** | **63.5** | **58.3** | **262.5** | **42.8** | **23.9** | **8.5** | **0.0** | **75.2** |
| CS-49S/HS | 52.8 | 57.3 | 63.1 | 75.1 | 248.3 | 72.7 | 68.0 | 63.5 | 58.3 | 262.5 | 42.8 | 23.9 | 8.5 | 0.0 | 75.2 |
| **0.23u TOTAL** | **0.0** | **0.2** | **0.8** | **1.9** | **2.8** | **3.5** | **7.7** | **13.9** | **30.6** | **55.7** | **51.0** | **66.3** | **85.7** | **96.0** | **299.0** |
| CS-99DB | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 6.4 | 12.6 | 29.2 | 48.1 | 49.6 | 66.3 | 85.7 | 96.0 | 297.6 |
| CS-99SB | 0.0 | 0.2 | 0.8 | 1.9 | 2.8 | 3.5 | 1.3 | 1.4 | 1.4 | 7.5 | 1.3 | 0.0 | 0.0 | 0.0 | 1.3 |
| **0.25u TOTAL** | **15.7** | **12.7** | **11.5** | **8.3** | **48.2** | **9.3** | **7.9** | **7.3** | **8.2** | **32.8** | **10.7** | **11.7** | **9.6** | **11.8** | **43.8** |
| 0.25u 1P4M | 9.6 | 10.1 | 8.7 | 5.9 | 34.3 | 7.1 | 5.9 | 5.4 | 6.3 | 24.7 | 7.3 | 8.3 | 9.2 | 11.3 | 36.1 |
| 0.25u 1P5M | 0.0 | 1.2 | 1.6 | 1.4 | 4.2 | 0.4 | 0.1 | 0.1 | 0.1 | 0.7 | 0.1 | 0.1 | 0.1 | 0.2 | 0.5 |
| CS-44E72 (5LM) | 5.4 | 0.7 | 0.6 | 0.6 | 7.3 | 0.5 | 0.5 | 0.5 | 0.4 | 1.9 | 0.3 | 0.3 | 0.3 | 0.3 | 1.2 |
| CS-49N/NS | 0.7 | 0.7 | 0.6 | 0.4 | 2.3 | 1.3 | 1.4 | 1.4 | 1.4 | 5.4 | 3.0 | 3.0 | 0.0 | 0.0 | 6.0 |
| **0.35u TOTAL** | **47.4** | **47.8** | **50.8** | **51.1** | **197.1** | **50.5** | **48.2** | **48.2** | **48.1** | **195.0** | **40.9** | **41.0** | **41.6** | **38.5** | **162.0** |
| 0.35u 1P3M | 0.8 | 1.5 | 1.4 | 1.1 | 4.8 | 0.8 | 0.8 | 0.8 | 0.9 | 3.4 | 0.8 | 0.8 | 0.8 | 0.8 | 3.2 |
| CS-34 (3LM) | 1.5 | 1.6 | 2.1 | 2.0 | 7.2 | 1.5 | 1.6 | 1.6 | 1.5 | 6.2 | 1.1 | 1.2 | 1.2 | 1.1 | 4.6 |
| CS-39S | 45.0 | 44.7 | 47.3 | 48.0 | 185.0 | 48.0 | 45.6 | 45.6 | 45.6 | 184.8 | 39.0 | 39.0 | 39.6 | 36.6 | 154.2 |
| CS-49NSD | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.2 | 0.1 | 0.1 | 0.1 | 0.6 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| EE7 (3LM) | 0.1 | 0.0 | 0.0 | 0.0 | 0.1 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| **TOTAL FAB** | **239.2** | **249.5** | **267.8** | **276.1** | **1032.6** | **288.4** | **302.2** | **323.3** | **342.9** | **1256.8** | **346.1** | **368.4** | **402.6** | **428.8** | **1545.8** |

## THREE-YEAR PLAN
## WAFER FABRICATION GROUP COMMITS (K, 8")
### BY GROUP BY FAB

| | 1Q01 | 2Q01 | 3Q01 | 4Q01 | 2001 | 1Q02 | 2Q02 | 3Q02 | 4Q02 | 2002 | 1Q03 | 2Q03 | 3Q03 | 4Q03 | 2003 |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **CPG** | **110.5** | **117.3** | **124.9** | **119.1** | **471.8** | **132.1** | **133.4** | **137.9** | **135.2** | **538.7** | **121.4** | **125.0** | **135.5** | **148.5** | **530.3** |
| TSMC | 0.0 | 0.1 | 0.1 | 0.1 | 0.3 | 0.1 | 0.1 | 0.1 | 0.1 | 0.5 | 0.1 | 0.1 | 0.1 | 0.1 | 0.4 |
| EPSON | 0.1 | 0.1 | 0.1 | 0.1 | 0.5 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| FAB 14/15 | 11.6 | 12.4 | 11.9 | 11.1 | 47.0 | 9.3 | 9.0 | 8.3 | 7.9 | 34.5 | 7.1 | 7.2 | 6.7 | 6.5 | 27.6 |
| Fab 25 | 61.7 | 58.4 | 62.1 | 61.7 | 243.9 | 61.0 | 58.7 | 58.5 | 53.0 | 231.2 | 30.7 | 26.9 | 30.9 | 34.5 | 123.0 |
| Fab 30 | 26.0 | 32.6 | 38.4 | 36.8 | 133.8 | 46.0 | 52.8 | 54.7 | 58.9 | 212.5 | 62.9 | 63.9 | 65.0 | 64.9 | 256.7 |
| Fab8A | 0.9 | 1.3 | 1.4 | 1.4 | 5.0 | 1.2 | 1.2 | 1.2 | 1.2 | 4.8 | 1.1 | 1.1 | 1.0 | 1.0 | 4.2 |
| Fab8B | 9.7 | 11.9 | 10.7 | 7.7 | 40.0 | 8.4 | 7.7 | 9.1 | 13.0 | 38.2 | 19.5 | 25.9 | 31.8 | 41.4 | 118.5 |
| SONY | 0.6 | 0.4 | 0.2 | 0.1 | 1.3 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| 0.13u Fdry #1 - | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 6.0 | 3.8 | 5.9 | 1.1 | 16.9 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| **LATTICE** | **6.8** | **6.7** | **6.7** | **6.7** | **27.1** | **6.7** | **6.7** | **6.7** | **6.7** | **27.0** | **6.7** | **6.7** | **6.7** | **6.7** | **27.0** |
| Fab 25 | 0.1 | 0.0 | 0.0 | 0.0 | 0.1 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| FAB 14/15 | 6.7 | 6.7 | 6.7 | 6.7 | 27.0 | 6.7 | 6.7 | 6.7 | 6.7 | 27.0 | 6.7 | 6.7 | 6.7 | 6.7 | 27.0 |
| **LEGERITY** | **19.4** | **19.7** | **20.5** | **20.6** | **80.1** | **21.1** | **23.4** | **24.9** | **25.4** | **94.8** | **25.9** | **26.9** | **27.9** | **28.7** | **109.5** |
| FAB 14/15 | 19.4 | 19.7 | 20.5 | 20.6 | 80.1 | 21.1 | 23.4 | 24.9 | 25.4 | 94.8 | 25.9 | 26.9 | 27.9 | 28.7 | 109.5 |
| **MEMORY** | **102.4** | **105.8** | **115.7** | **129.7** | **453.6** | **128.5** | **138.6** | **153.8** | **175.5** | **596.3** | **192.0** | **209.8** | **232.4** | **244.9** | **879.0** |
| FASL 4 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.5 | 0.5 | 5.5 | 16.0 | 28.0 | 37.8 | 87.3 |
| FAB 14/15 | 3.9 | 3.0 | 3.9 | 3.8 | 14.6 | 2.8 | 2.9 | 3.0 | 2.9 | 11.5 | 2.8 | 2.8 | 2.8 | 2.8 | 11.2 |
| FASL - GMD | 8.7 | 10.7 | 14.3 | 24.2 | 57.9 | 27.0 | 25.8 | 27.8 | 36.0 | 116.6 | 38.5 | 41.2 | 44.1 | 46.7 | 170.5 |
| FASL - IWATE | 17.0 | 16.3 | 16.6 | 17.6 | 67.5 | 15.1 | 14.5 | 13.4 | 14.0 | 57.0 | 17.1 | 17.9 | 18.9 | 18.9 | 72.6 |
| FASL 1 | 45.0 | 44.7 | 47.3 | 48.0 | 185.0 | 48.0 | 45.6 | 45.6 | 45.6 | 184.8 | 39.0 | 41.2 | 44.8 | 44.9 | 169.8 |
| FASL 2 | 27.9 | 31.1 | 33.6 | 35.6 | 128.1 | 35.7 | 36.9 | 37.7 | 40.4 | 150.6 | 43.0 | 42.3 | 42.1 | 41.6 | 168.9 |
| FASL 3 | 0.0 | 0.0 | 0.0 | 0.5 | 0.5 | 0.0 | 12.9 | 26.3 | 36.2 | 75.4 | 46.2 | 48.5 | 51.9 | 52.3 | 198.8 |
| **TOTAL FAB** | **239.2** | **249.5** | **267.8** | **276.1** | **1032.6** | **288.4** | **302.2** | **323.3** | **342.9** | **1256.8** | **346.1** | **368.4** | **402.6** | **428.8** | **1545.8** |

## THREE-YEAR PLAN
## WAFER FABRICATION GROUP COMMITS (K, 8")
### BY DIVISION BY FAB

| **PRODUCT LINE** | 1Q01 | 2Q01 | 3Q01 | 4Q01 | 2001 | 1Q02 | 2Q02 | 3Q02 | 4Q02 | 2002 | 1Q03 | 2Q03 | 3Q03 | 4Q03 | 2003 |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| **C[illegible]MD** | **85.9** | **88.1** | **96.8** | **94.6** | **365.3** | **109.1** | **111.0** | **114.5** | **108.6** | **443.1** | **89.7** | **87.0** | **92.1** | **95.8** | **364.6** |
| 0.[illegible]d Fdry #1 - (BULK) | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 6.0 | 3.8 | 5.9 | 1.1 | 16.9 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| Fab 25 | 59.9 | 55.5 | 58.4 | 57.8 | 231.6 | 57.1 | 54.3 | 53.8 | 48.5 | 213.7 | 26.8 | 23.1 | 27.1 | 30.9 | 107.9 |
| Fab 30 | 26.0 | 32.6 | 38.4 | 36.8 | 133.8 | 46.0 | 52.8 | 54.7 | 58.9 | 212.5 | 62.9 | 63.9 | 65.0 | 64.9 | 256.7 |
| **EPD** | **7.2** | **9.6** | **10.1** | **9.8** | **36.7** | **9.4** | **9.8** | **9.9** | **9.4** | **38.6** | **8.8** | **8.9** | **8.7** | **8.5** | **35.0** |
| EPSON | 0.1 | 0.1 | 0.1 | 0.1 | 0.5 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| FAB 14/15 | 4.2 | 5.2 | 4.9 | 4.3 | 18.6 | 3.9 | 3.7 | 3.3 | 2.9 | 13.8 | 2.8 | 2.8 | 2.6 | 2.4 | 10.7 |
| Fab 25 | 1.8 | 2.9 | 3.7 | 3.9 | 12.3 | 3.9 | 4.4 | 4.7 | 4.5 | 17.5 | 3.9 | 3.8 | 3.8 | 3.6 | 15.1 |
| Fab8A | 0.1 | 0.3 | 0.4 | 0.4 | 1.2 | 0.3 | 0.3 | 0.3 | 0.3 | 1.3 | 0.3 | 0.3 | 0.3 | 0.3 | 1.3 |
| Fab8B | 0.3 | 0.6 | 0.8 | 1.0 | 2.7 | 1.3 | 1.4 | 1.6 | 1.7 | 5.9 | 1.8 | 2.0 | 2.0 | 2.2 | 8.0 |
| SONY | 0.6 | 0.4 | 0.2 | 0.1 | 1.3 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| **LATTICE** | **6.8** | **6.7** | **6.7** | **6.7** | **27.1** | **6.7** | **6.7** | **6.7** | **6.7** | **27.0** | **6.7** | **6.7** | **6.7** | **6.7** | **27.0** |
| FAB 14/15 | 6.7 | 6.7 | 6.7 | 6.7 | 27.0 | 6.7 | 6.7 | 6.7 | 6.7 | 27.0 | 6.7 | 6.7 | 6.7 | 6.7 | 27.0 |
| Fab 25 | 0.1 | 0.0 | 0.0 | 0.0 | 0.1 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| **LEGERITY** | **19.4** | **19.7** | **20.5** | **20.6** | **80.1** | **21.1** | **23.4** | **24.9** | **25.4** | **94.8** | **25.9** | **26.9** | **27.9** | **28.7** | **109.5** |
| FAB 14/15 | 19.4 | 19.7 | 20.5 | 20.6 | 80.1 | 21.1 | 23.4 | 24.9 | 25.4 | 94.8 | 25.9 | 26.9 | 27.9 | 28.7 | 109.5 |
| **NPD** | **8.1** | **8.3** | **8.1** | **8.0** | **32.5** | **6.5** | **6.5** | **6.3** | **6.3** | **25.6** | **6.1** | **6.1** | **6.3** | **6.3** | **24.9** |
| FAB 14/15 | 7.4 | 7.2 | 7.0 | 6.8 | 28.4 | 5.4 | 5.4 | 5.0 | 5.0 | 20.7 | 4.4 | 4.4 | 4.1 | 4.1 | 16.9 |
| Fab8A | 0.7 | 1.0 | 1.0 | 1.1 | 3.9 | 0.9 | 0.9 | 0.9 | 0.9 | 3.5 | 0.7 | 0.7 | 0.7 | 0.7 | 2.9 |
| Fab8B | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.1 | 0.1 | 0.4 | 0.4 | 0.9 | 0.9 | 0.9 | 1.4 | 1.4 | 4.7 |
| TSMC | 0.0 | 0.1 | 0.1 | 0.1 | 0.3 | 0.1 | 0.1 | 0.1 | 0.1 | 0.5 | 0.1 | 0.1 | 0.1 | 0.1 | 0.4 |
| **NVD** | **102.4** | **105.8** | **115.7** | **129.7** | **453.6** | **128.5** | **138.6** | **153.8** | **175.5** | **596.3** | **192.0** | **209.8** | **232.4** | **244.9** | **879.0** |
| FAB 14/15 | 3.9 | 3.0 | 3.9 | 3.8 | 14.6 | 2.8 | 2.9 | 3.0 | 2.9 | 11.5 | 2.8 | 2.8 | 2.8 | 2.8 | 11.2 |
| FASL - GMD | 8.7 | 10.7 | 14.3 | 24.2 | 57.9 | 27.0 | 25.8 | 27.8 | 36.0 | 116.6 | 38.5 | 41.2 | 44.1 | 46.7 | 170.5 |
| FASL - IWATE | 17.0 | 16.3 | 16.6 | 17.6 | 67.5 | 15.1 | 14.5 | 13.4 | 14.0 | 57.0 | 17.1 | 17.9 | 18.9 | 18.9 | 72.6 |
| FASL 1 | 45.0 | 44.7 | 47.3 | 48.0 | 185.0 | 48.0 | 45.6 | 45.6 | 45.6 | 184.8 | 39.0 | 41.2 | 44.8 | 44.9 | 169.8 |
| FASL 2 | 27.9 | 31.1 | 33.6 | 35.6 | 128.1 | 35.7 | 36.9 | 37.7 | 40.4 | 150.6 | 43.0 | 42.3 | 42.1 | 41.6 | 168.9 |
| FASL 3 | 0.0 | 0.0 | 0.0 | 0.5 | 0.5 | 0.0 | 12.9 | 26.3 | 36.2 | 75.4 | 46.2 | 48.5 | 51.9 | 52.3 | 198.8 |
| FASL 4 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 | 0.5 | 0.5 | 5.5 | 16.0 | 28.0 | 37.8 | 87.3 |
| **PPD** | **9.4** | **11.3** | **9.9** | **6.7** | **37.2** | **7.1** | **6.2** | **7.2** | **11.0** | **31.4** | **16.7** | **22.9** | **28.4** | **37.8** | **105.8** |
| Fab8B | 9.4 | 11.3 | 9.9 | 6.7 | 37.2 | 7.1 | 6.2 | 7.2 | 11.0 | 31.4 | 16.7 | 22.9 | 28.4 | 37.8 | 105.8 |
| **T[illegible]L FAB** | **239.2** | **249.5** | **267.8** | **276.1** | **1032.6** | **288.4** | **302.2** | **323.3** | **342.9** | **1256.8** | **346.1** | **368.4** | **402.6** | **428.8** | **1545.8** |